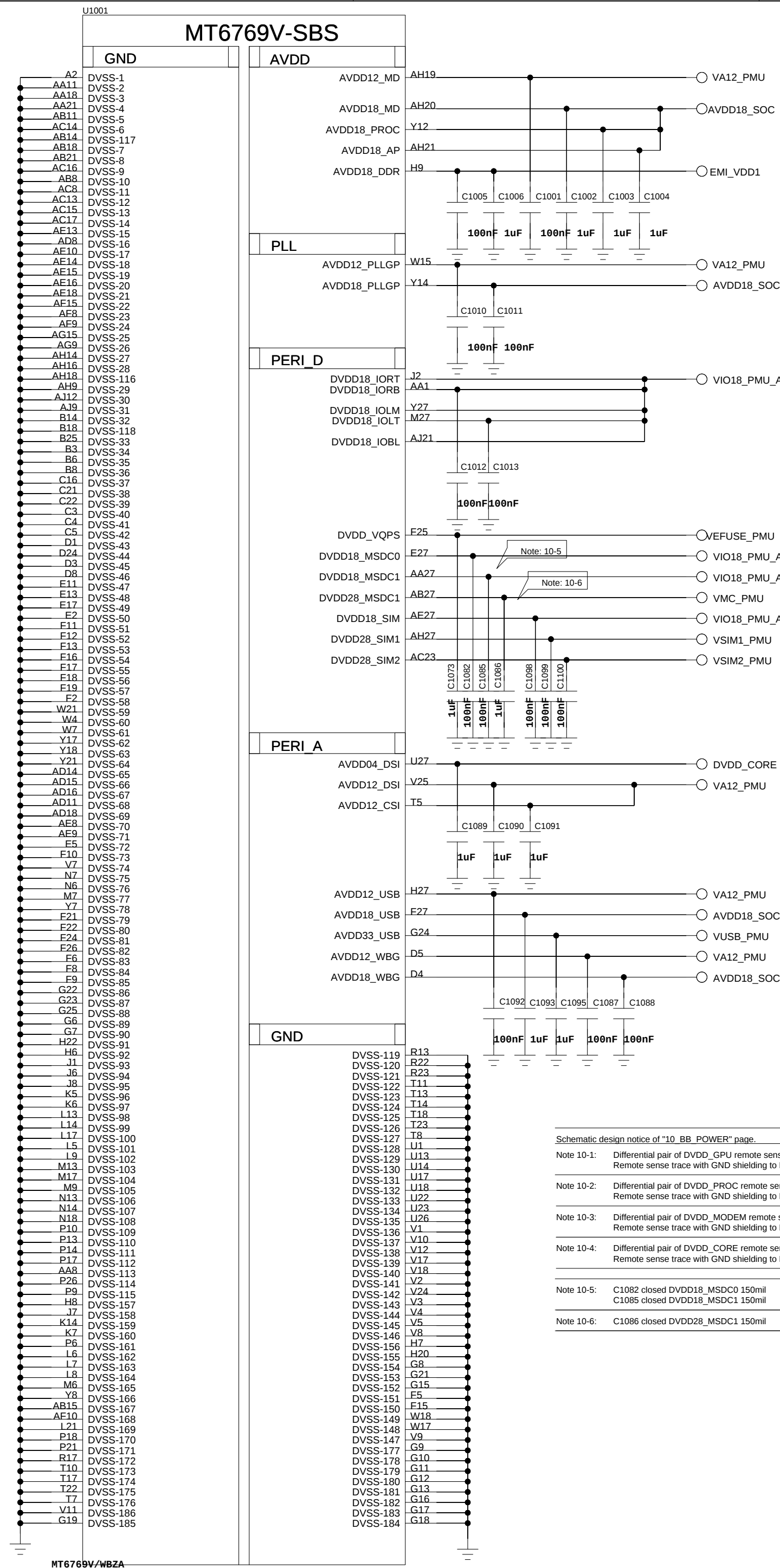
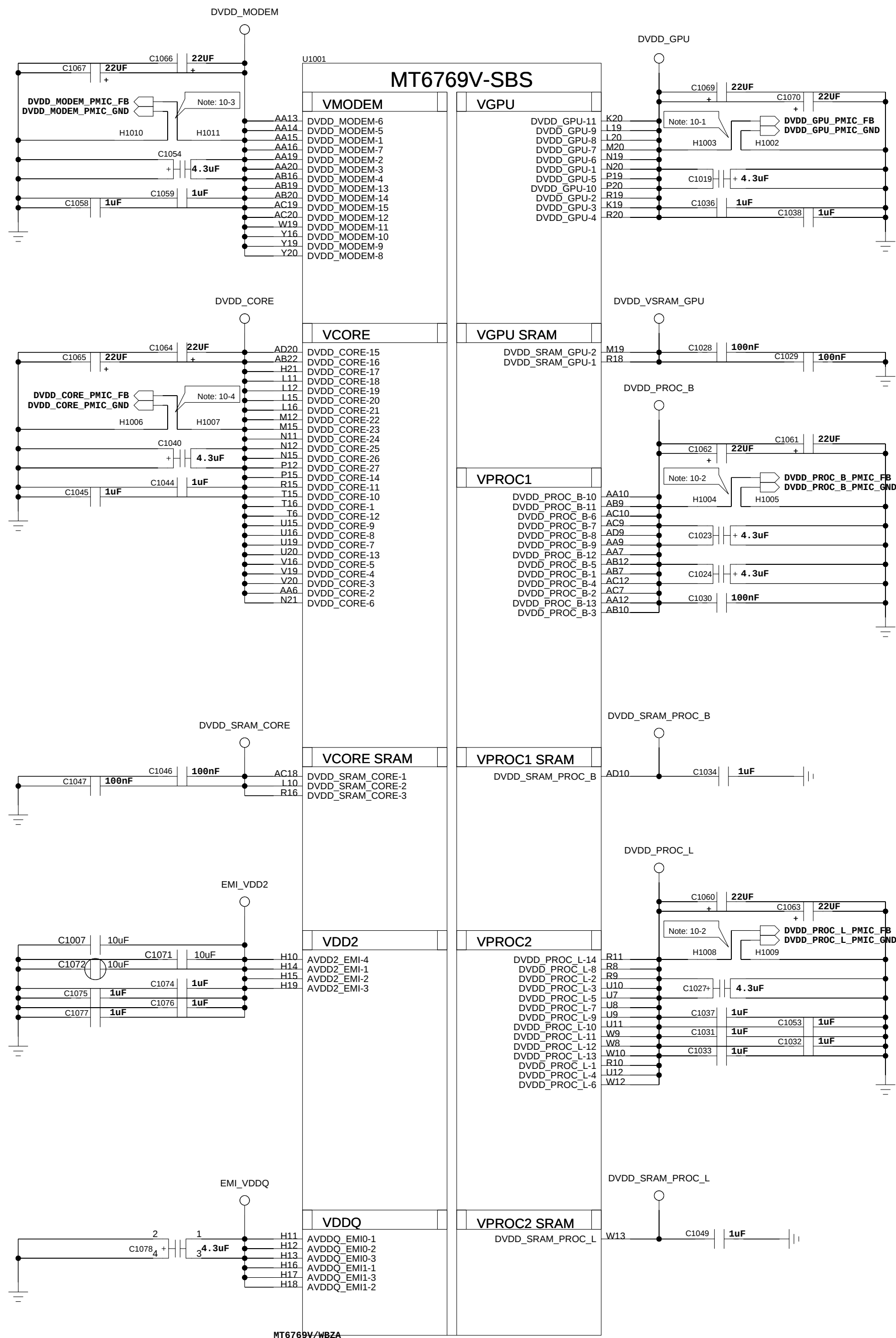


BB_POWER



REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

Schematic design notice of "10_BB_POWER" page.

Note 10-1: Differential pair of DVDD_GPU remote sense must be close to BB's ball
Remote sense trace with GND shielding to PMIC (Differential)

Note 10-2: Differential pair of DVDD_PROC remote sense must be close to BB's base. Remote sense trace with GND shielding to PMIC (Differential)

Note 10-3: Differential pair of DVDD_MODEM remote sense must be close to BB's ball
Remote sense trace with GND shielding to PMIC (Differential)

Note 10-4: Differential pair of DVDD_CORE remote sense must be close to BB's bal
Remote sense trace with GND shielding to PMIC (Differential)

Note 10-5: C1082 closed DVDD18_MSDC0 150mil

C1085 closed DVDD18_MSDC1 150mil

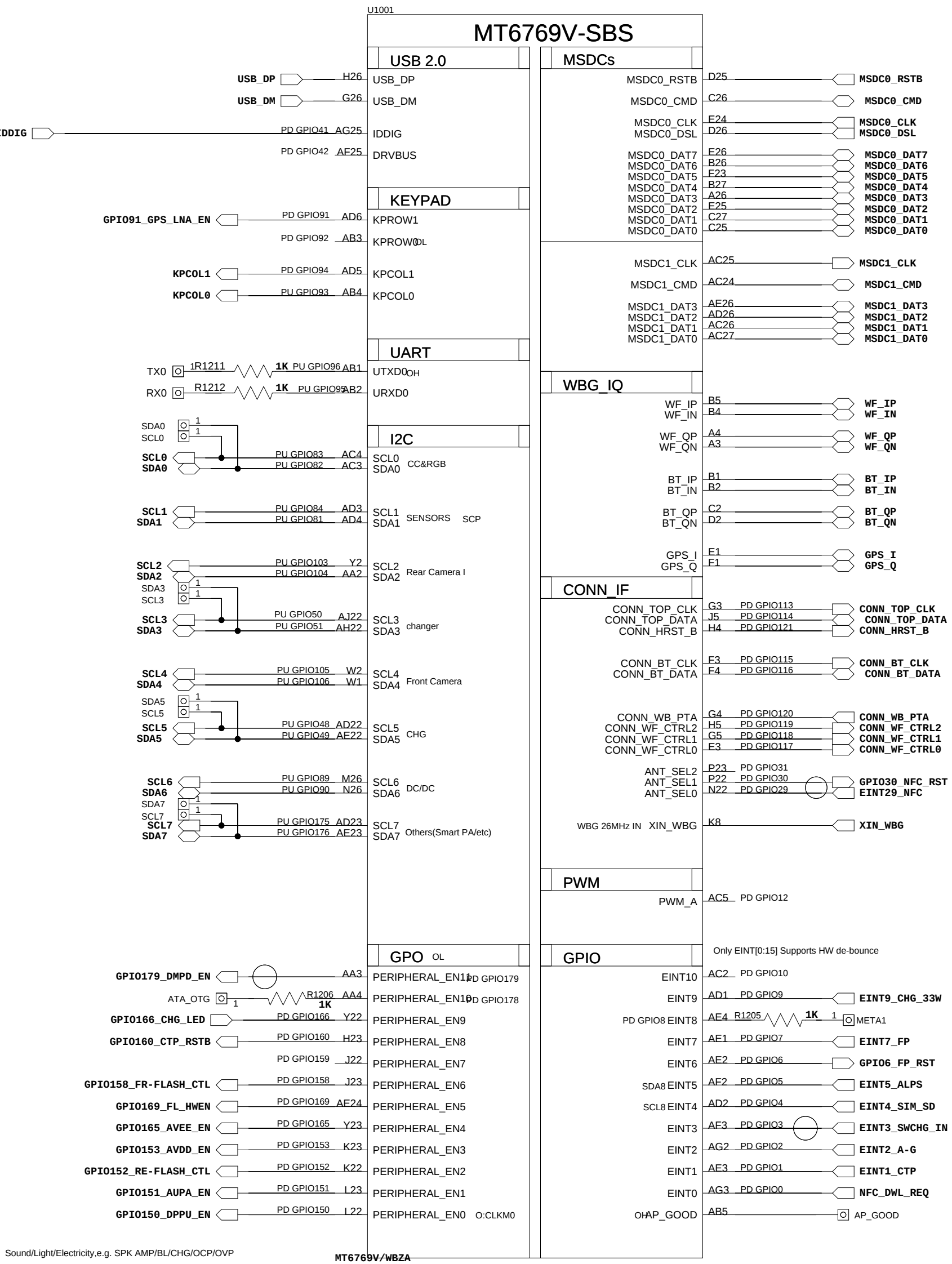
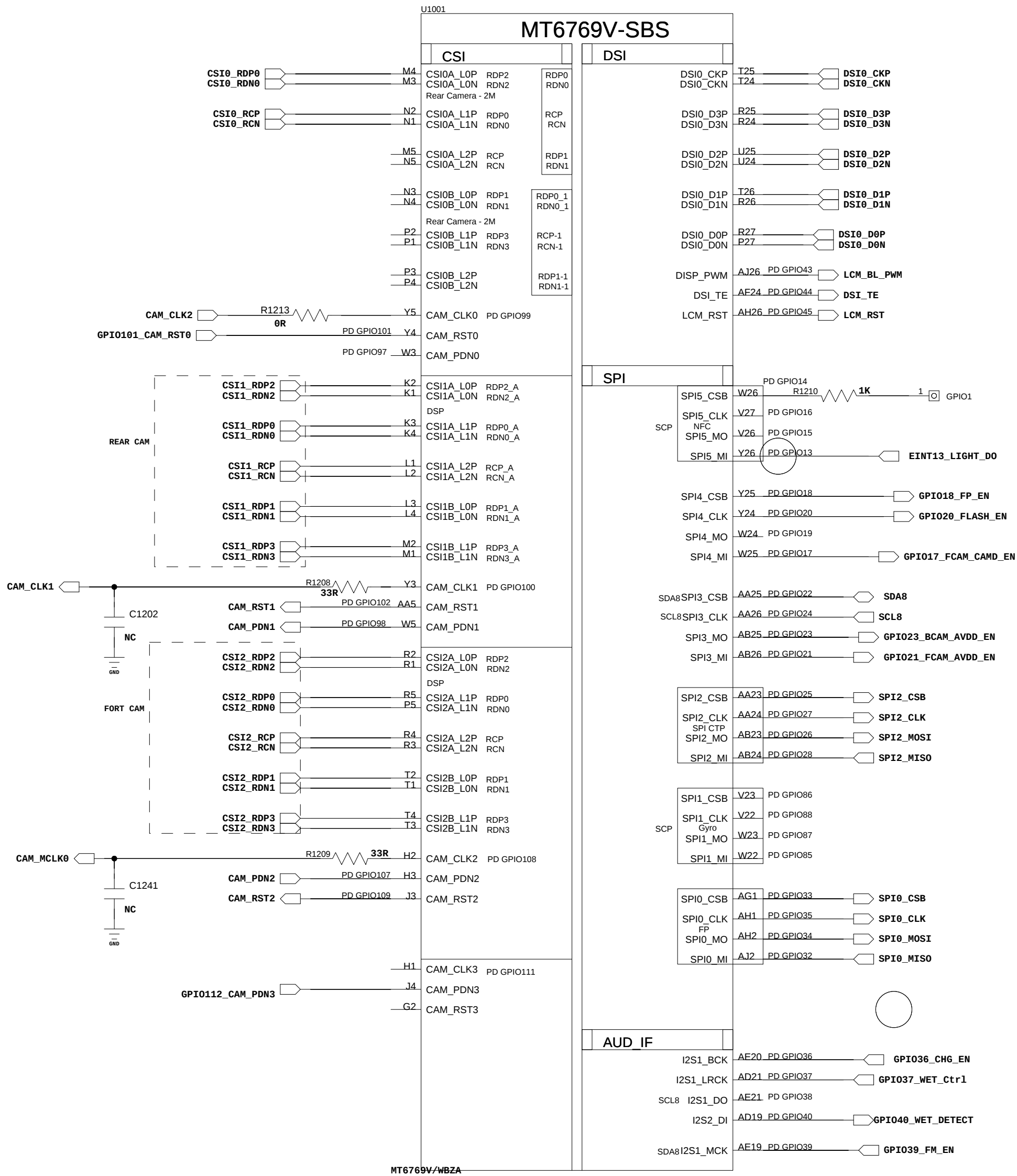
Note 10-6: C1086 closed DVDD28_MSDC1 150mil



Default

Default

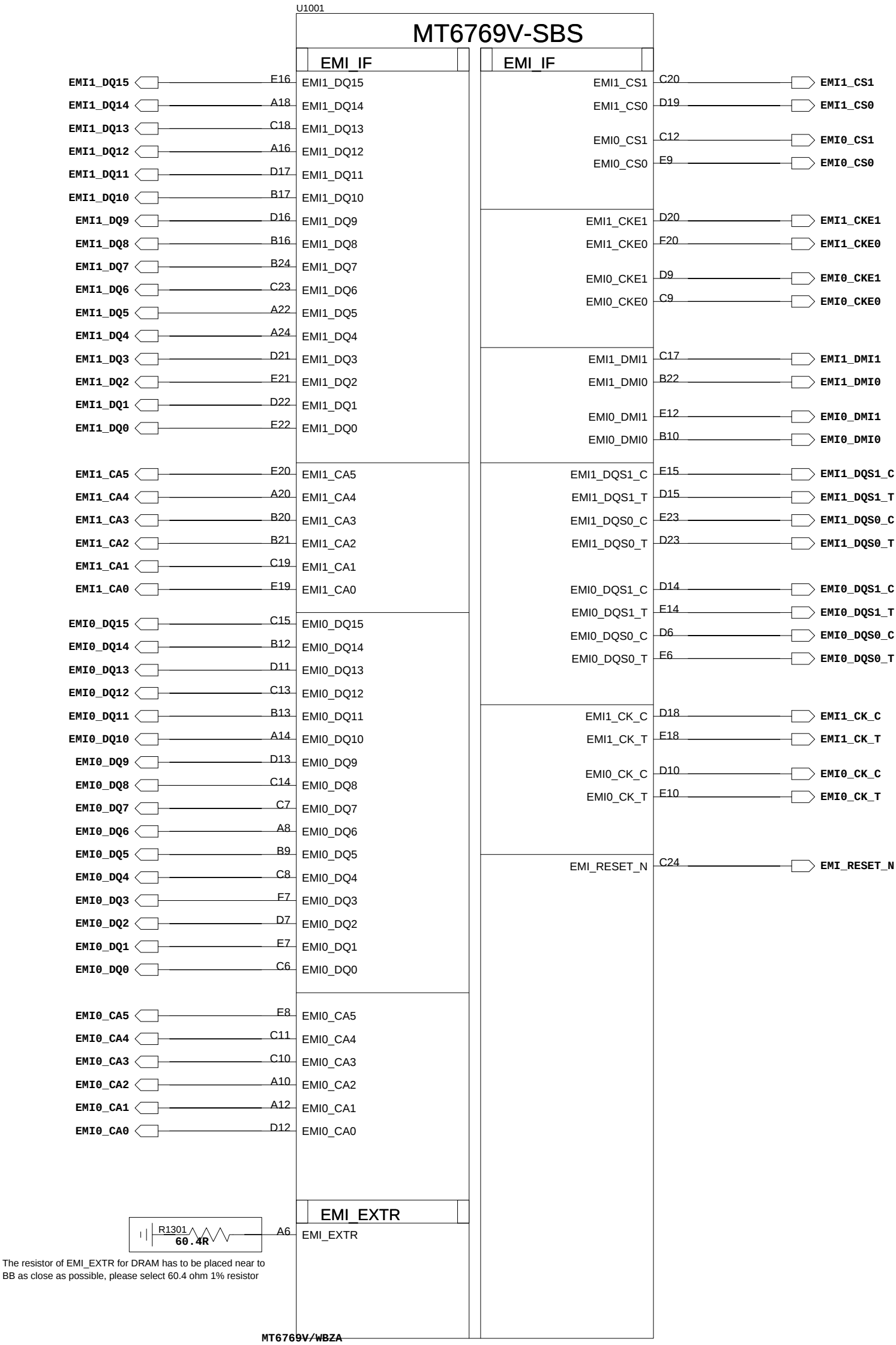
REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:



Sound/Light/Electricity.e.g. SPK AMP/BL/CHG/OC/OPP
enable Pin suggest to use PERIPHERAL_EN[0:5]

REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

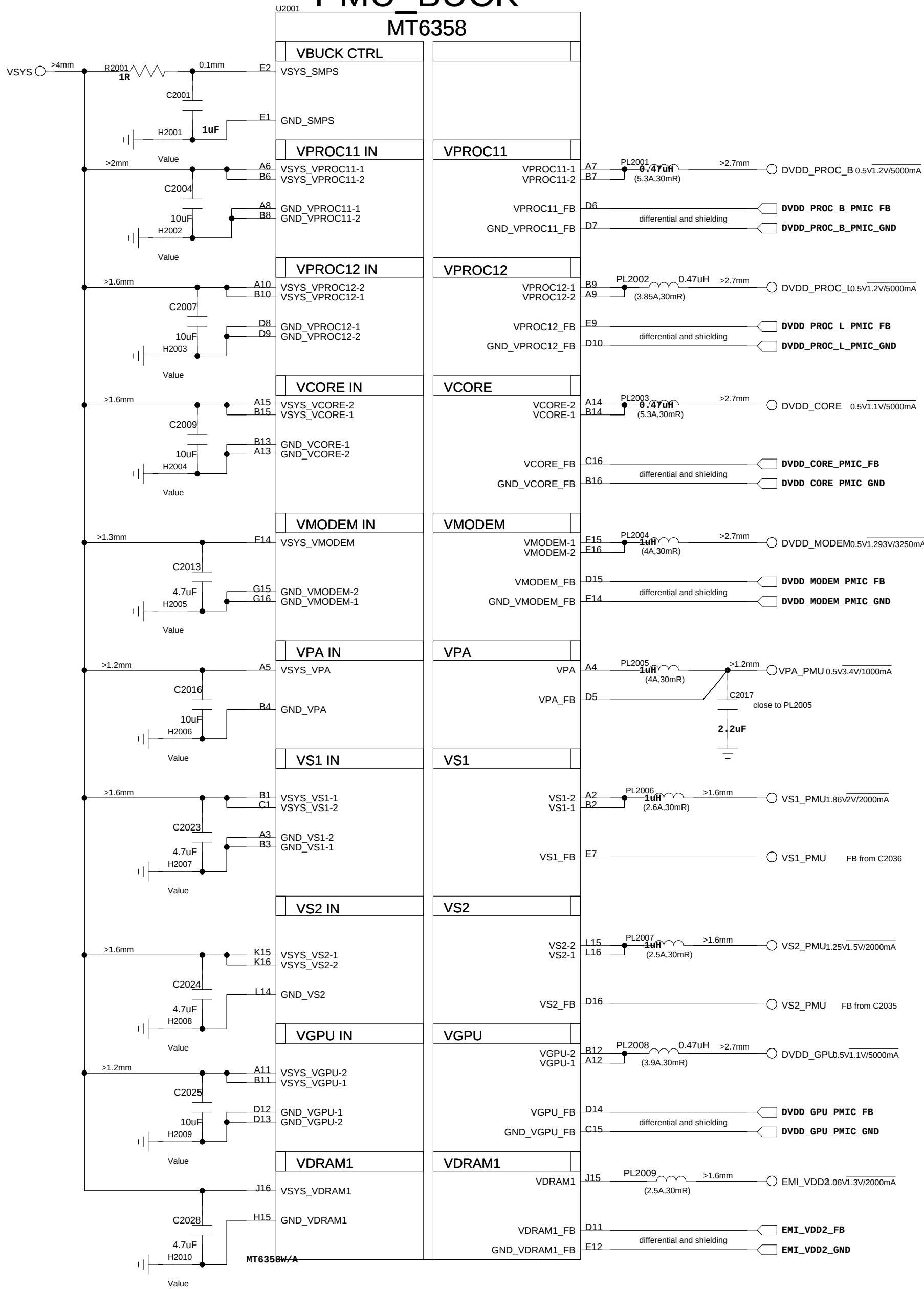
LPDDR4X_EMI_IF



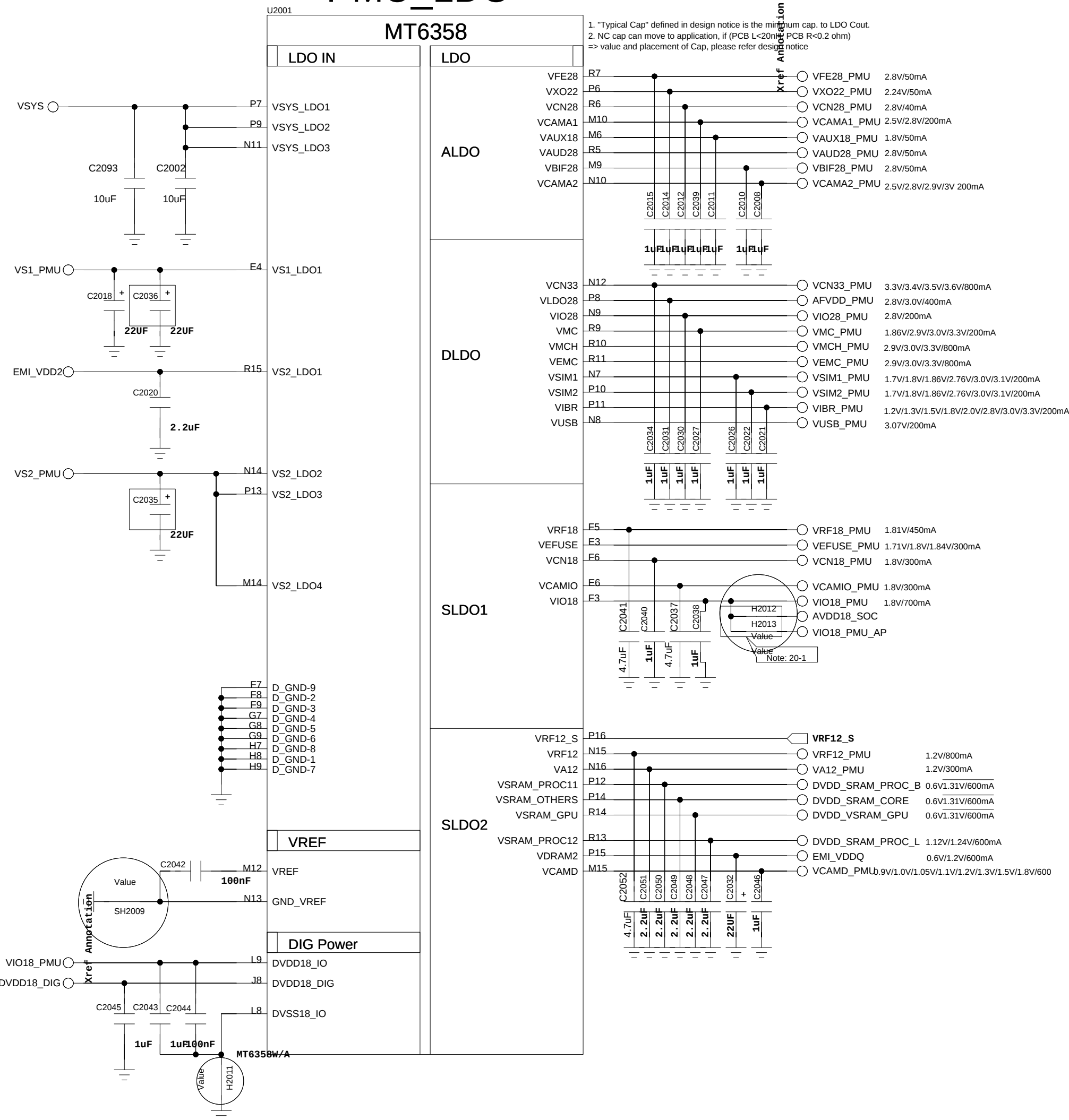
POWER_MT6358_I

REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

PMU BUCK



PMU LDO

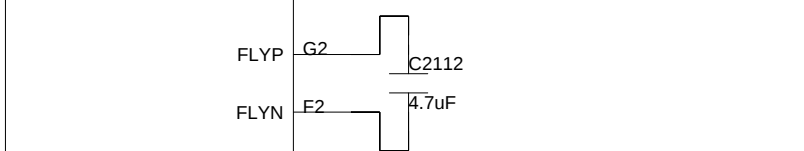
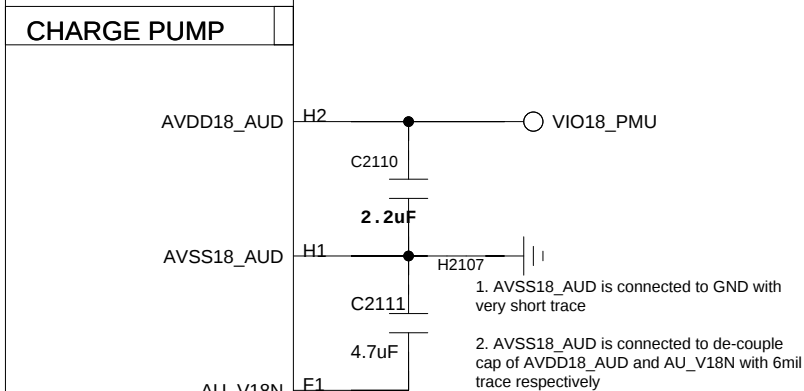
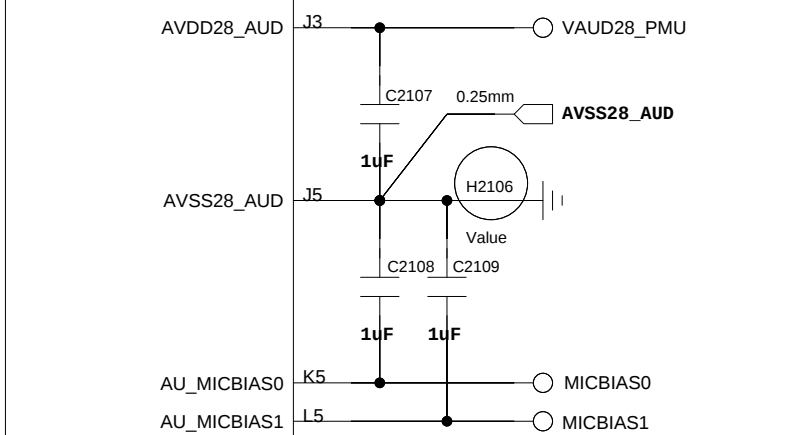
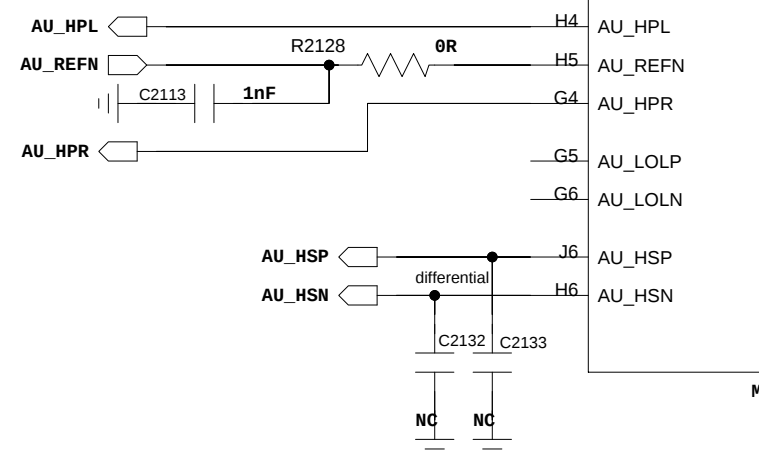
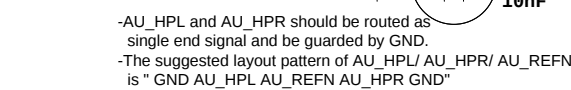
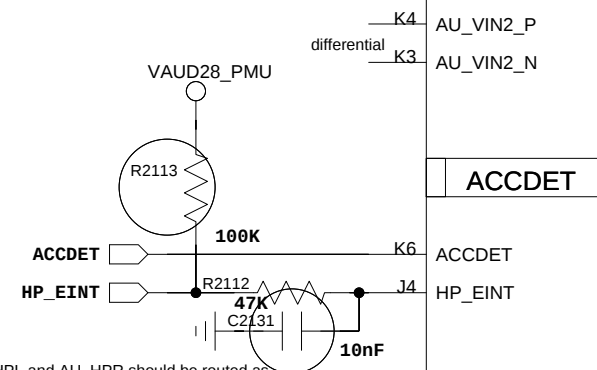
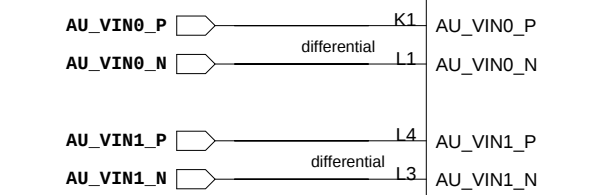
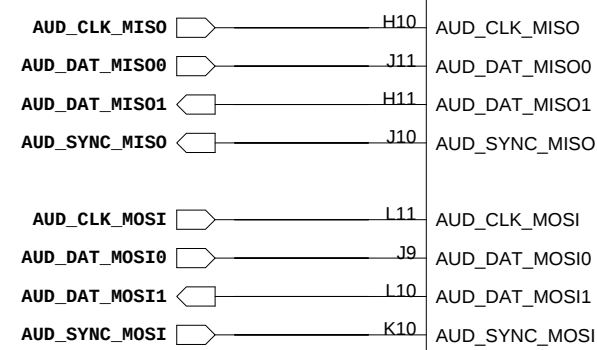
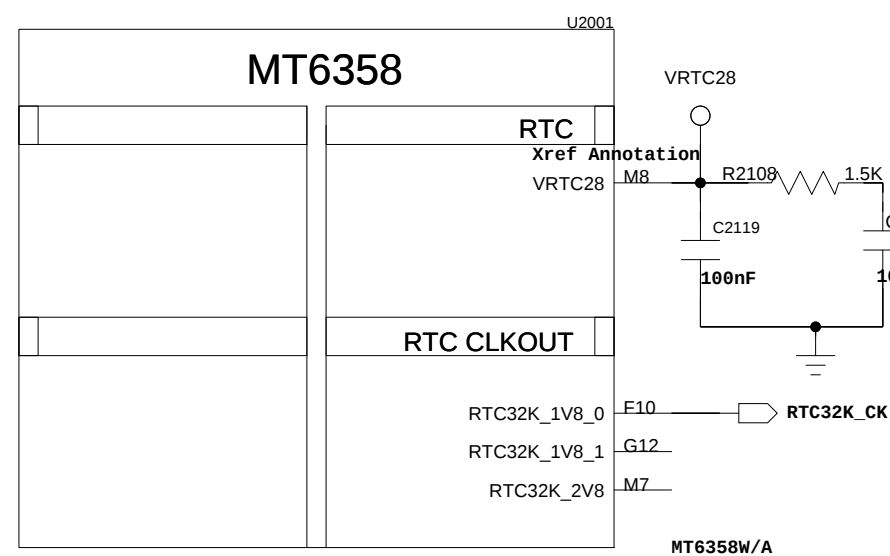
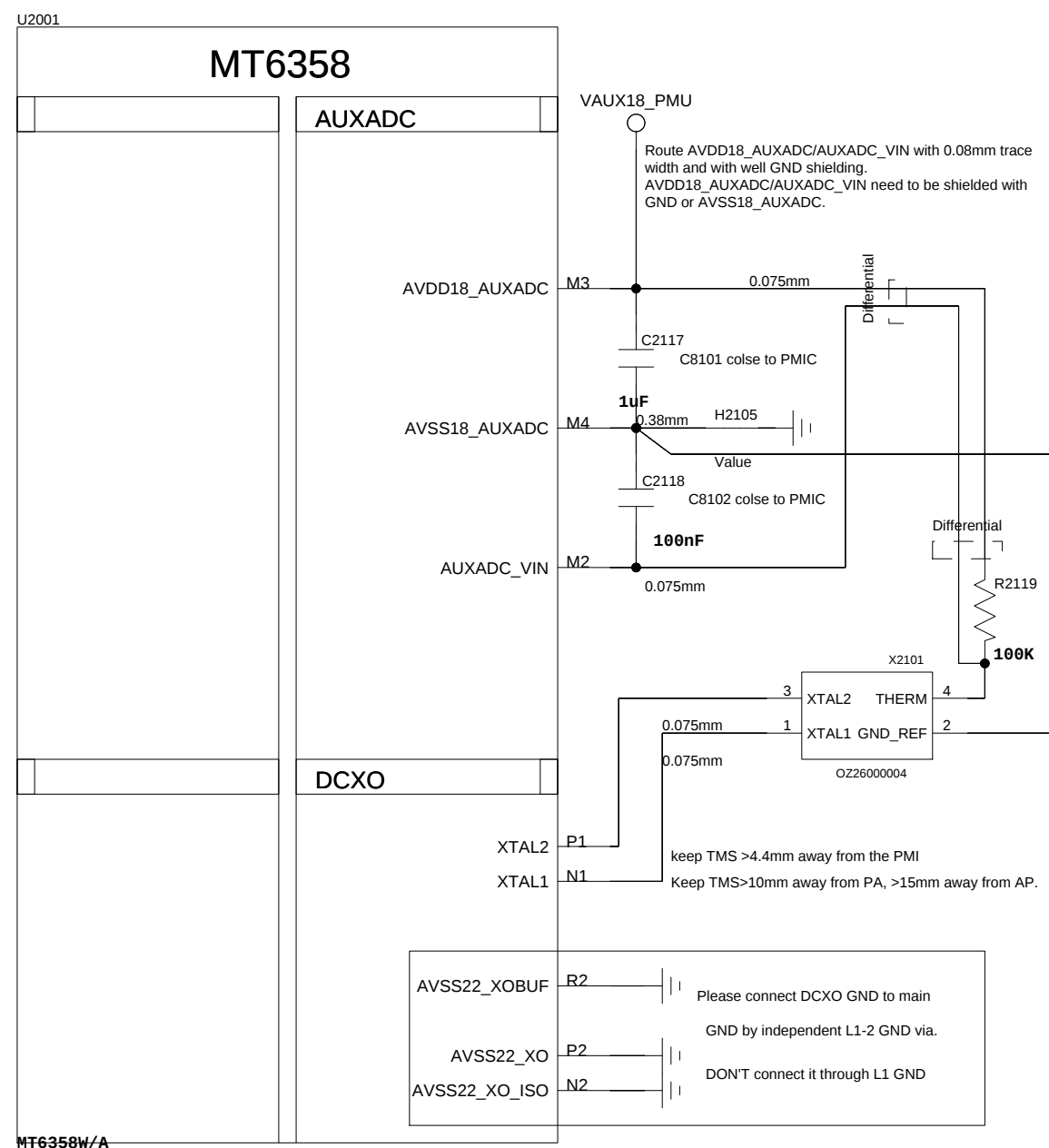
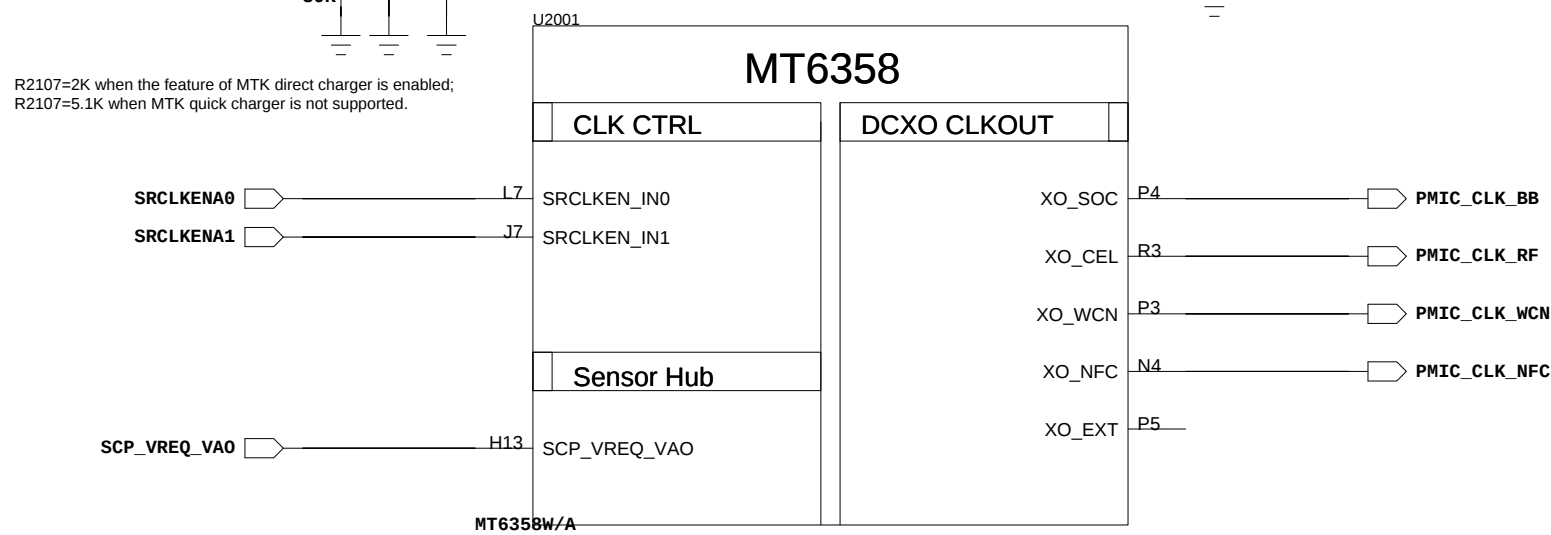
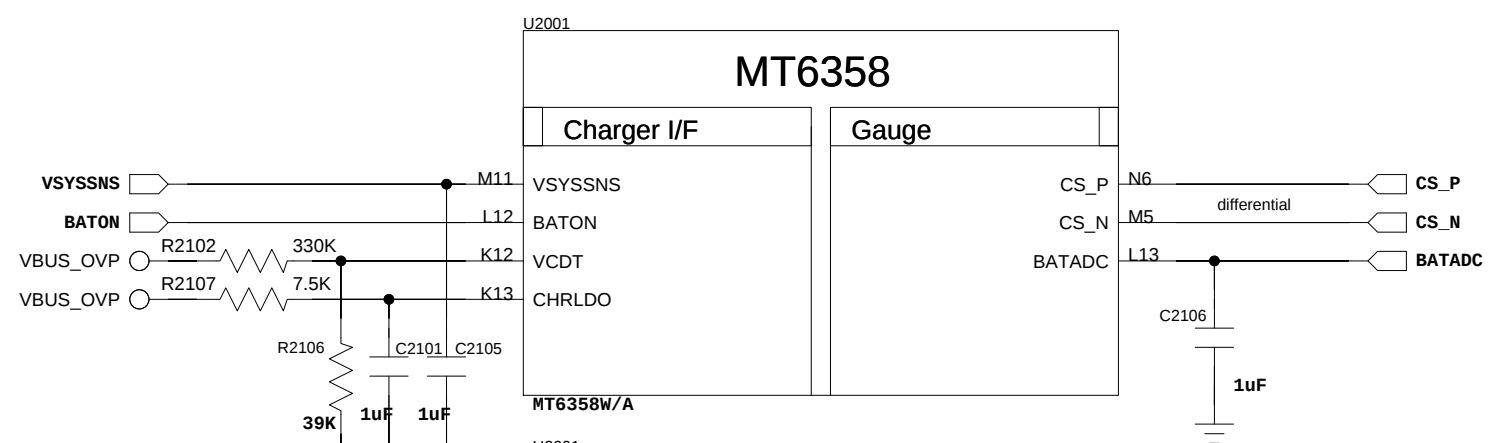
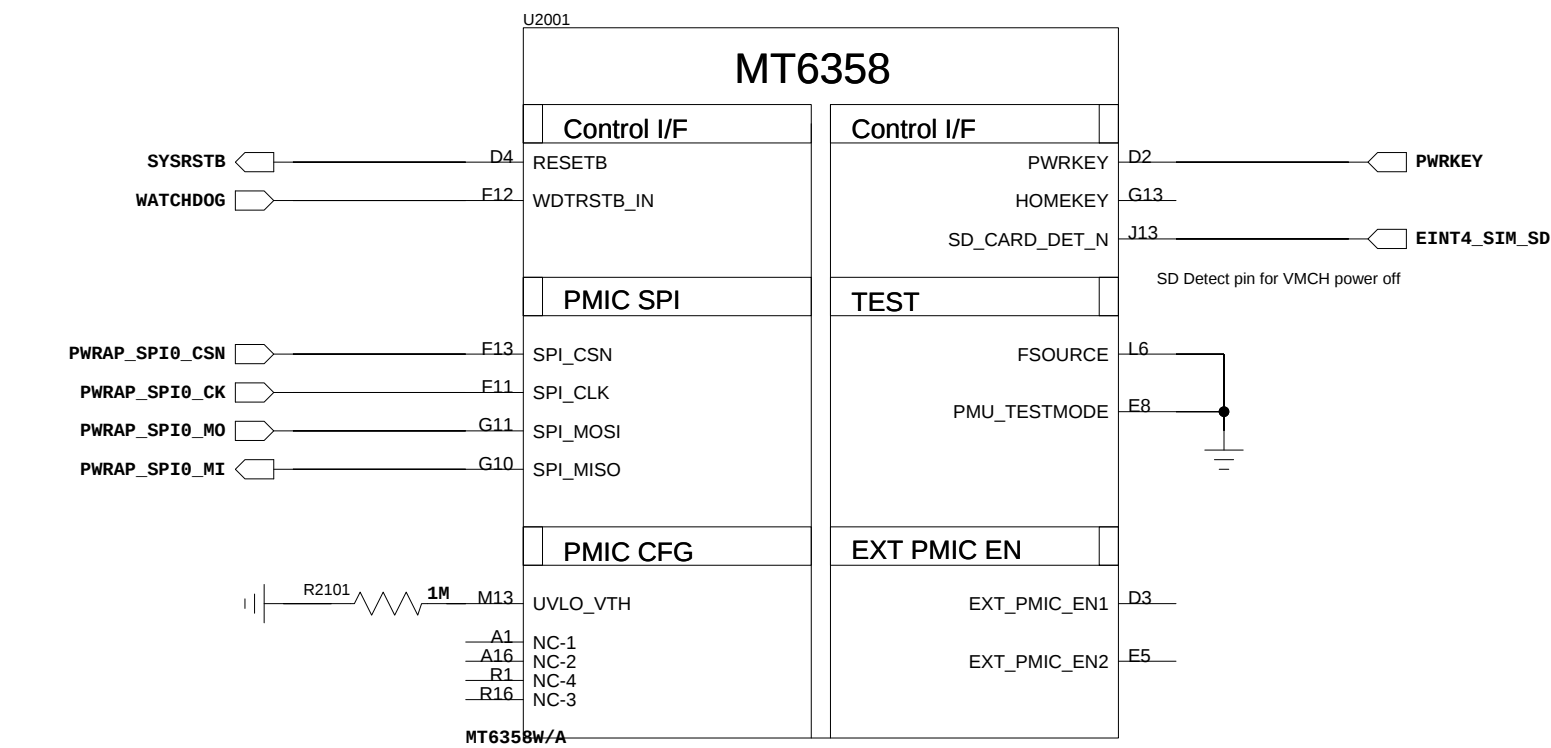


Schematic design notice of "21_POWER_MT6358-LDO" page.

Note 21-1: Please set H2012/H2013 close to C2038, making star connection between VIO18_PMU and AVDD18_SOC/VIO18_PMU_AP near to LDO cap. C2038.
Please also refer to MT6358 design notice for further detail design information

POWER_MT6358_II

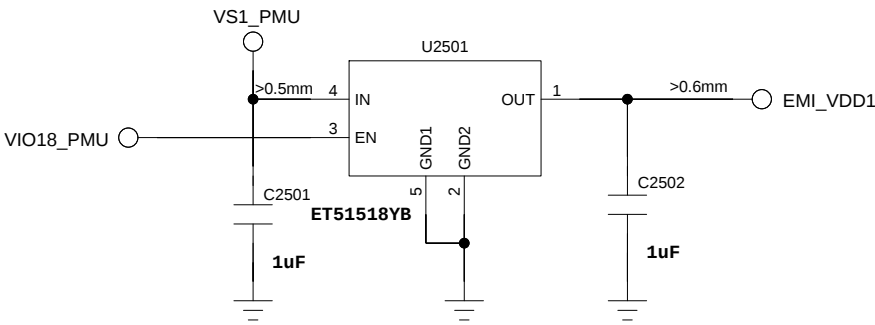
REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:



POWER_THIRD-PARTY-I

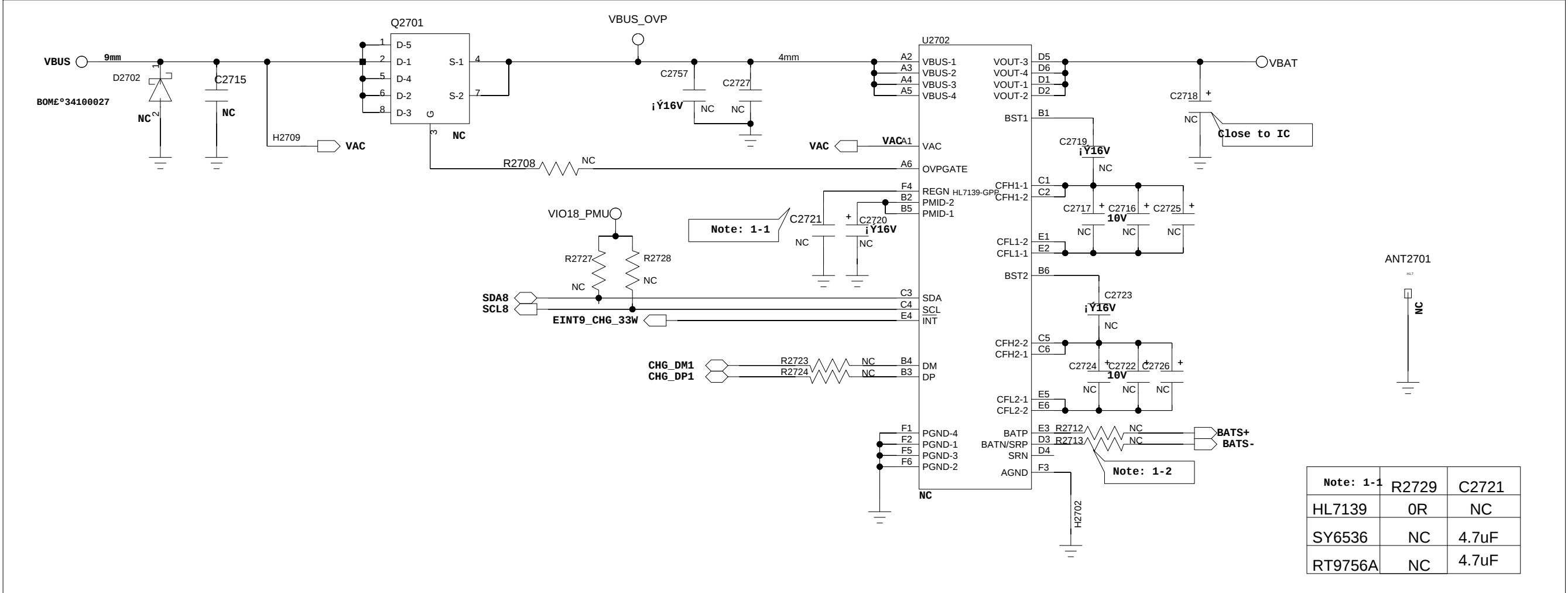
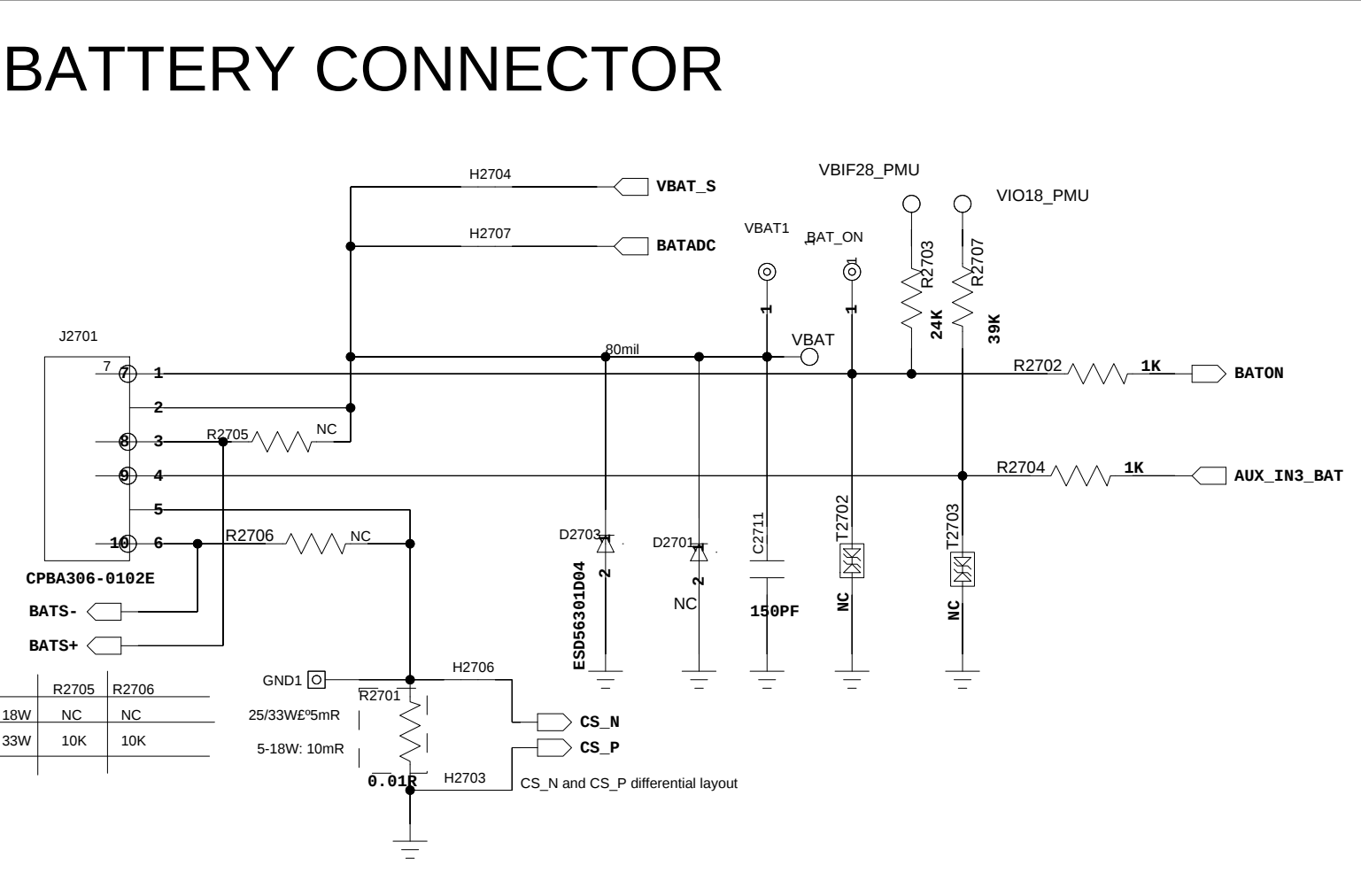
System supply

LPDDR4X VDD1 1.8V LDO



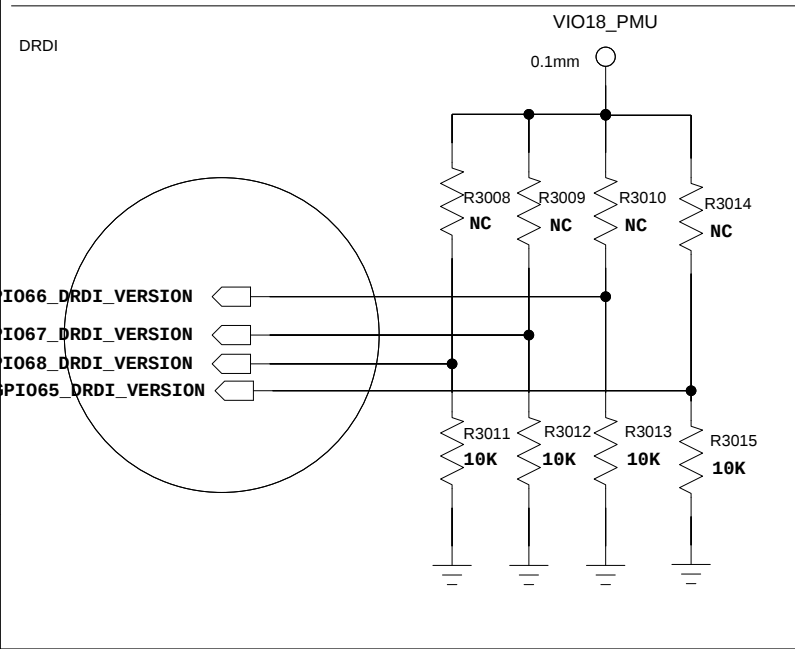
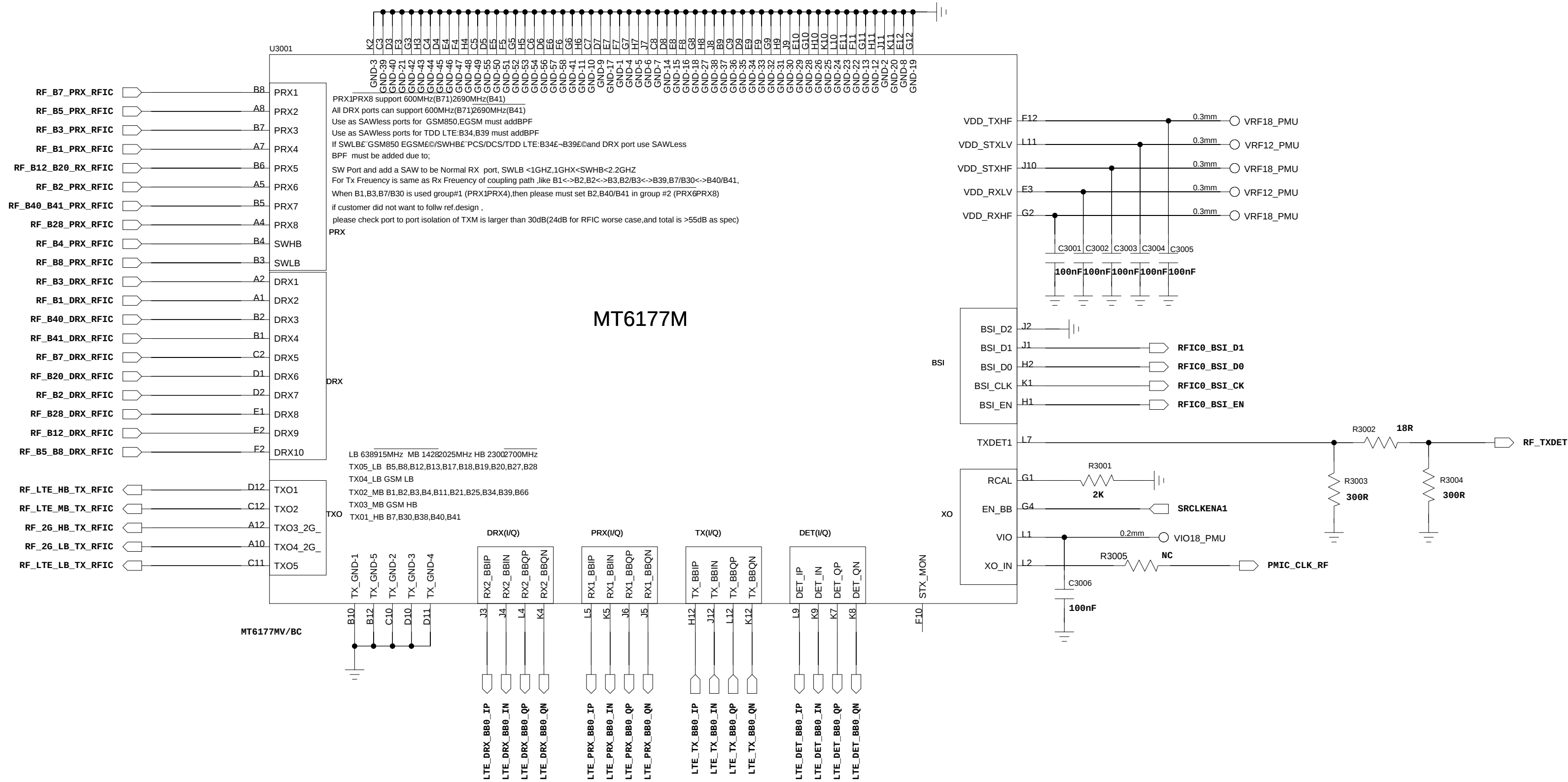
REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

REVISION RECORD			
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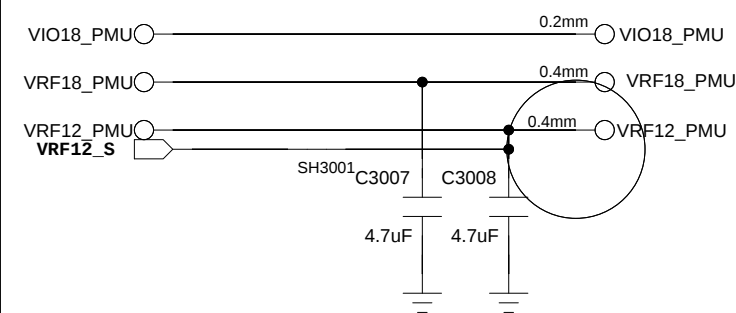


RF_MT6177M_PIN_OUT

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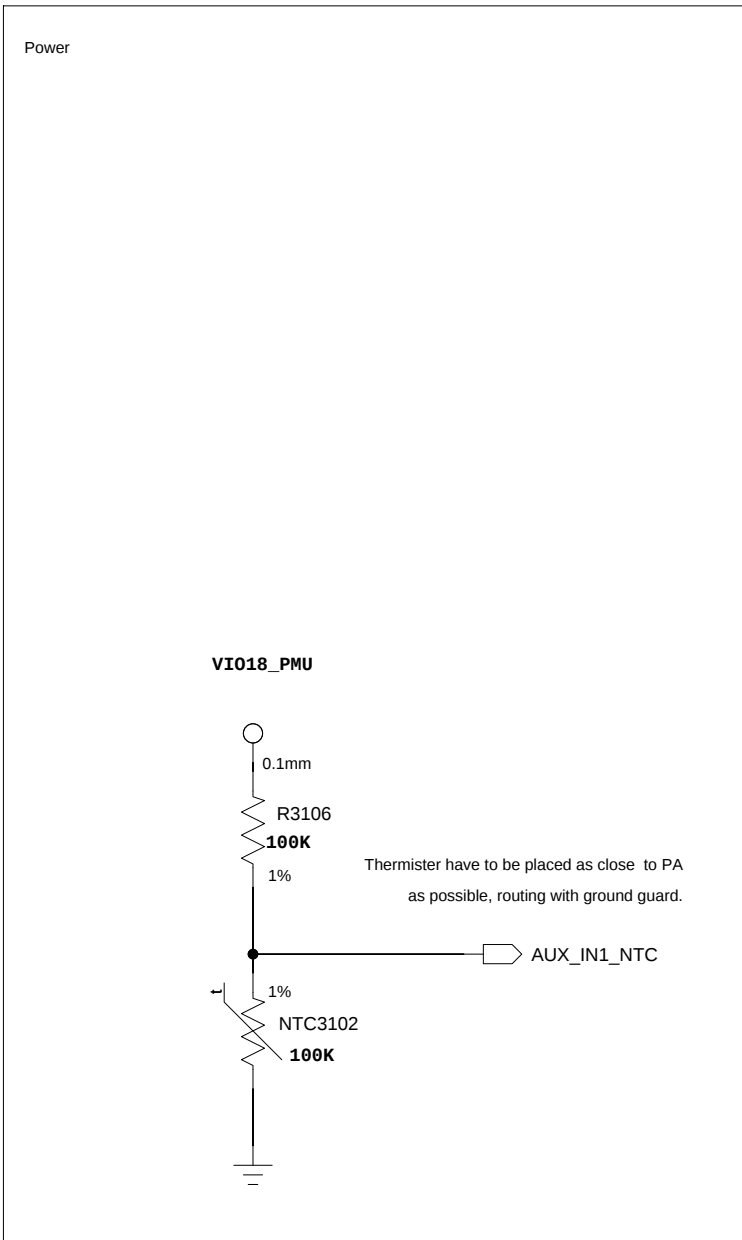


Power domain of MT6177M



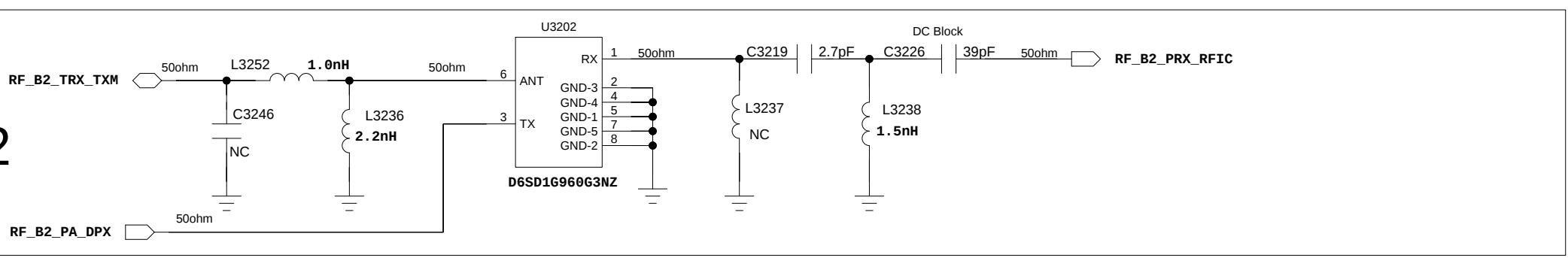
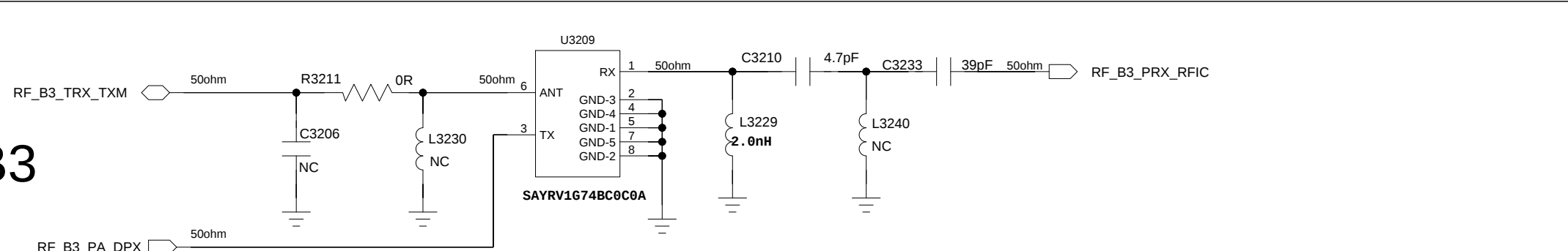
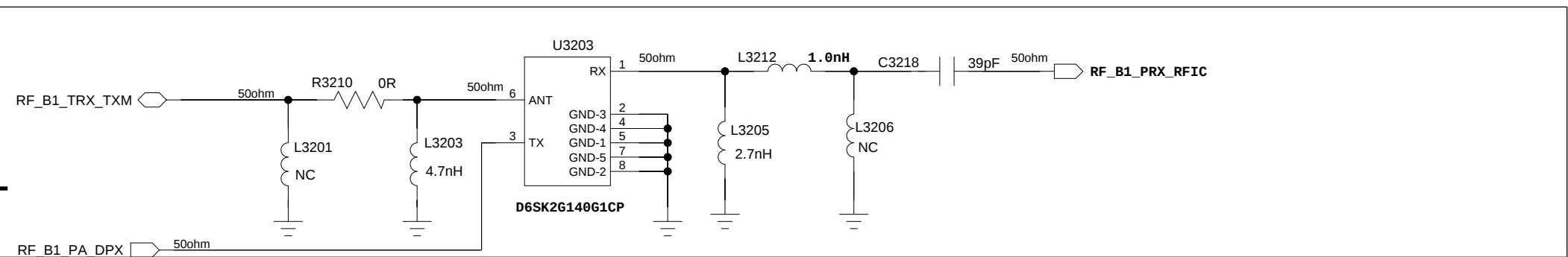
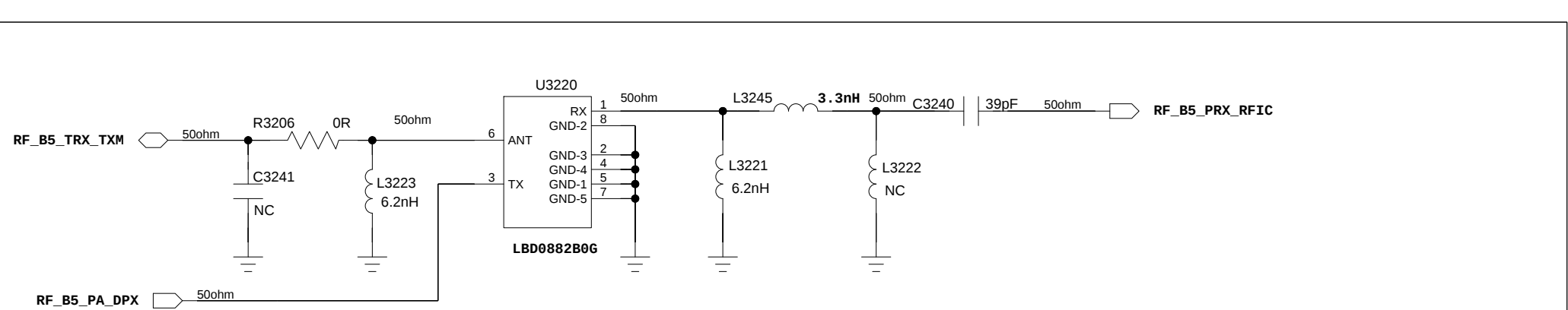
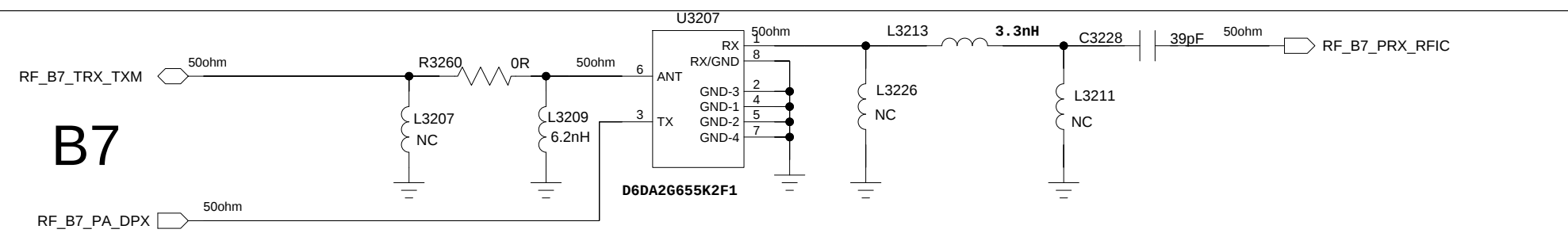
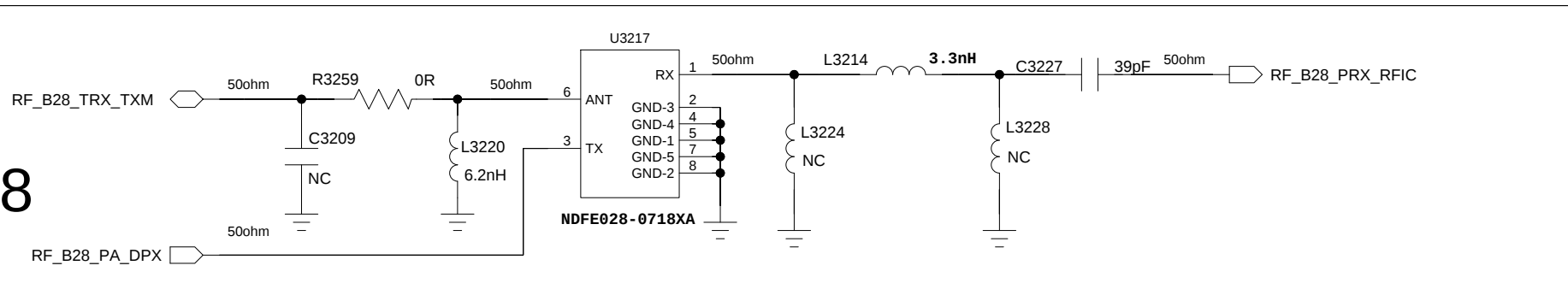
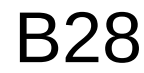
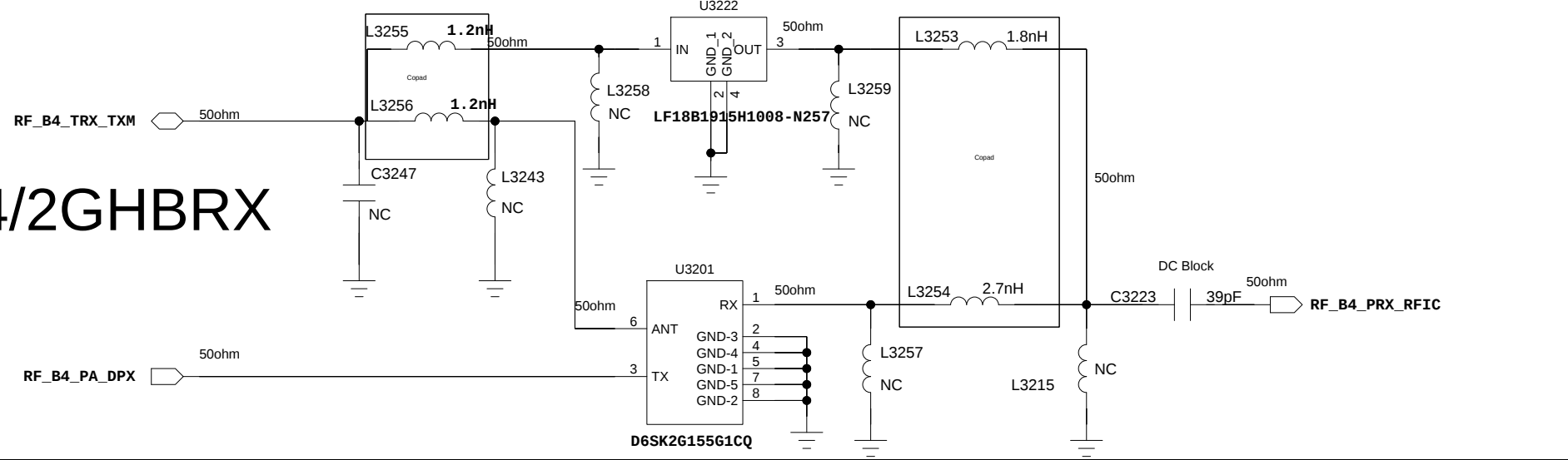
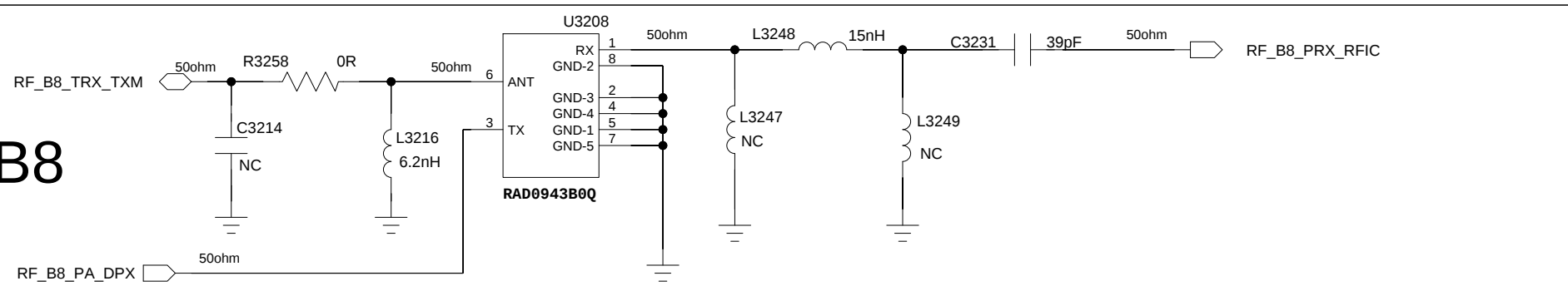
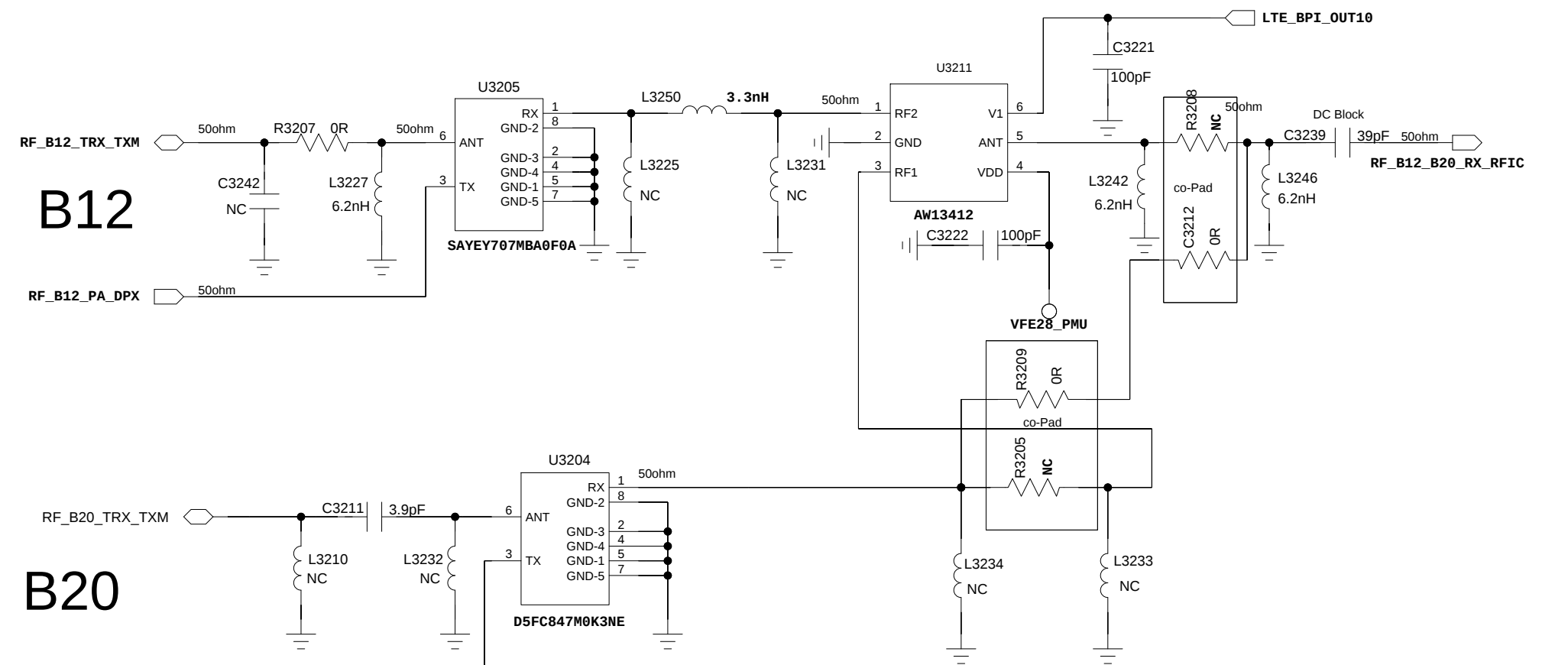
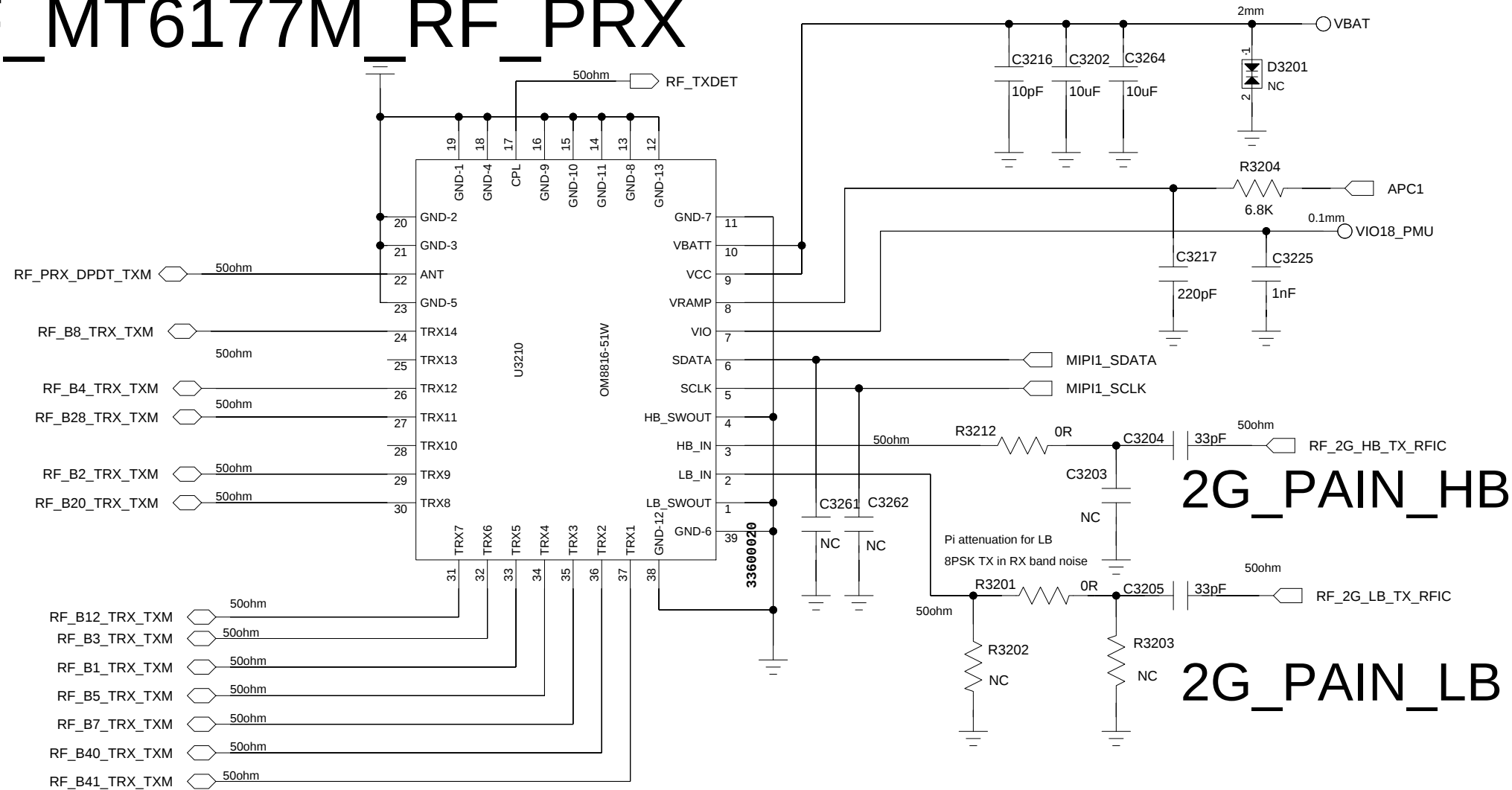
Star Power

REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

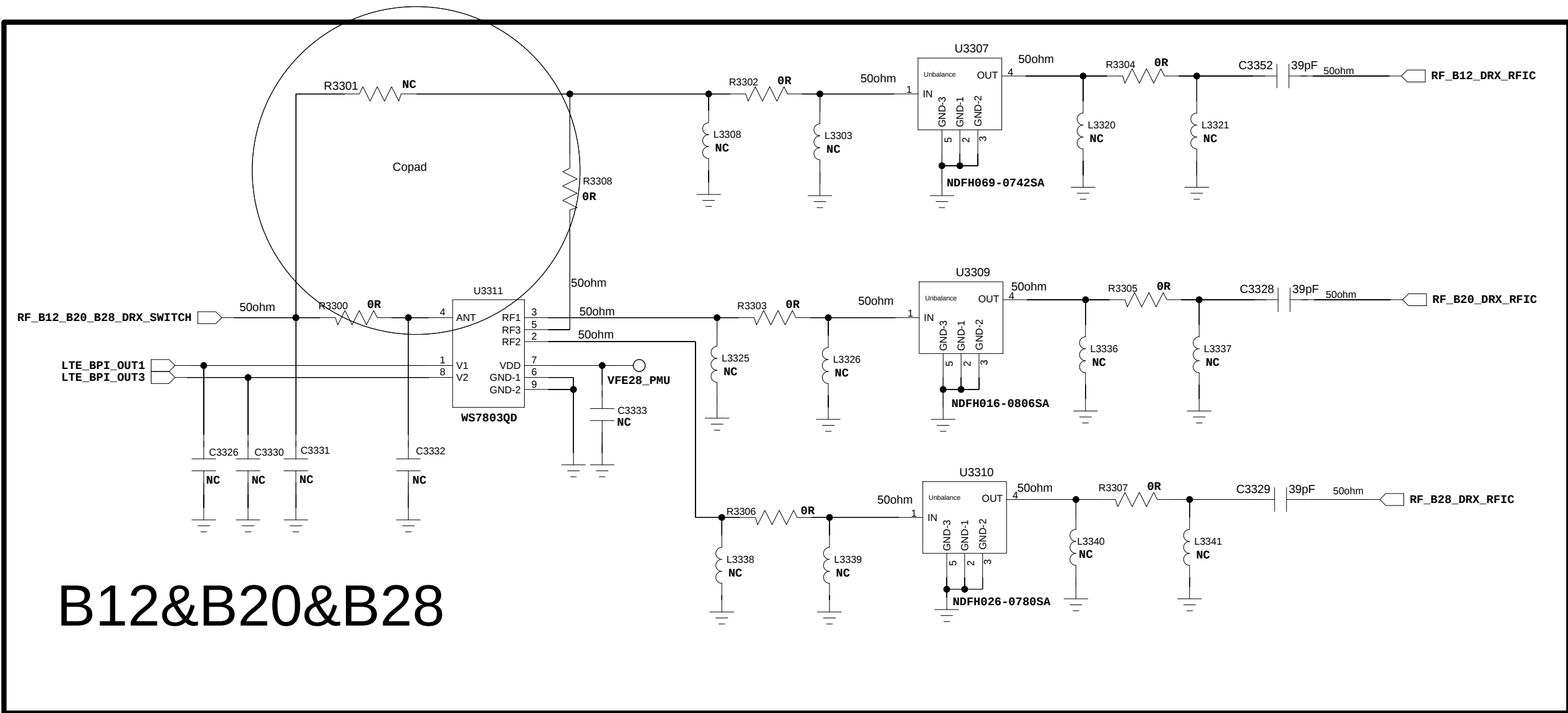
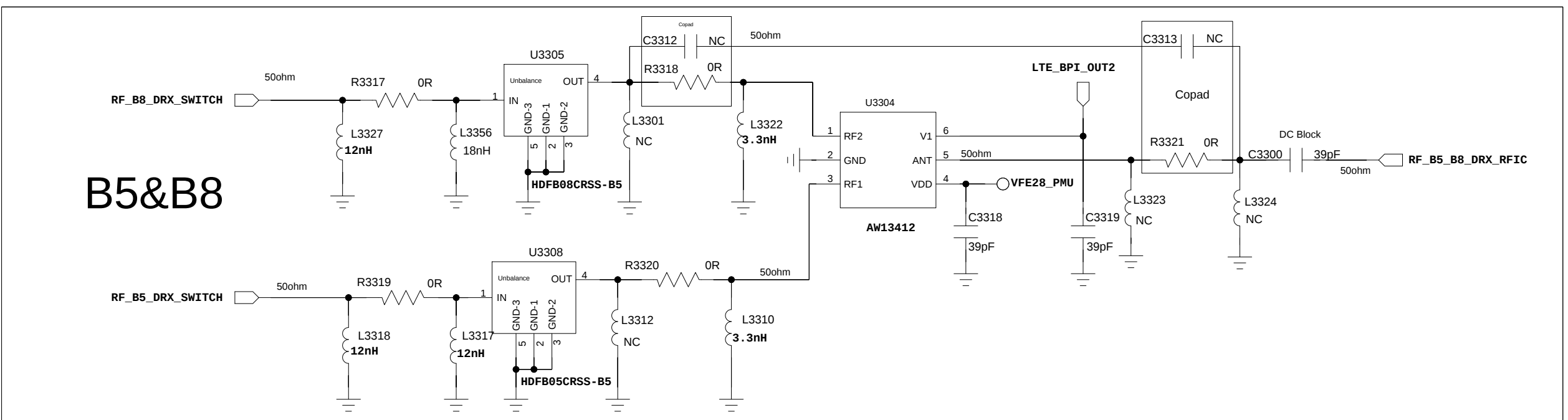
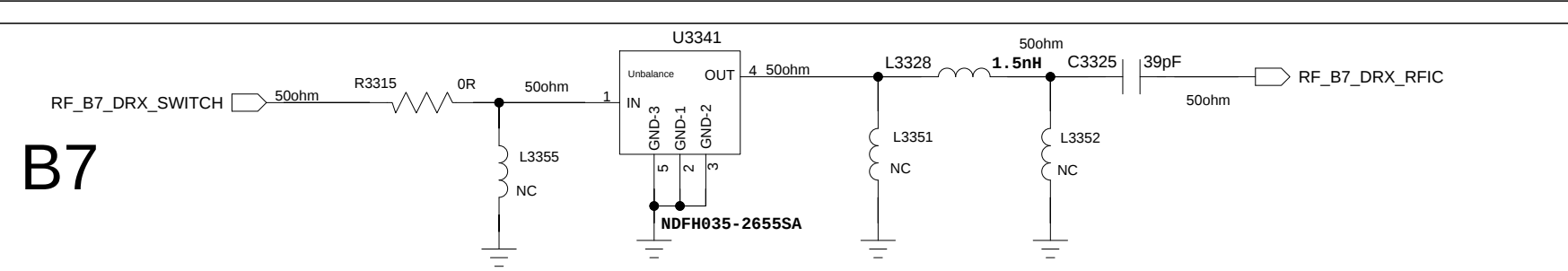
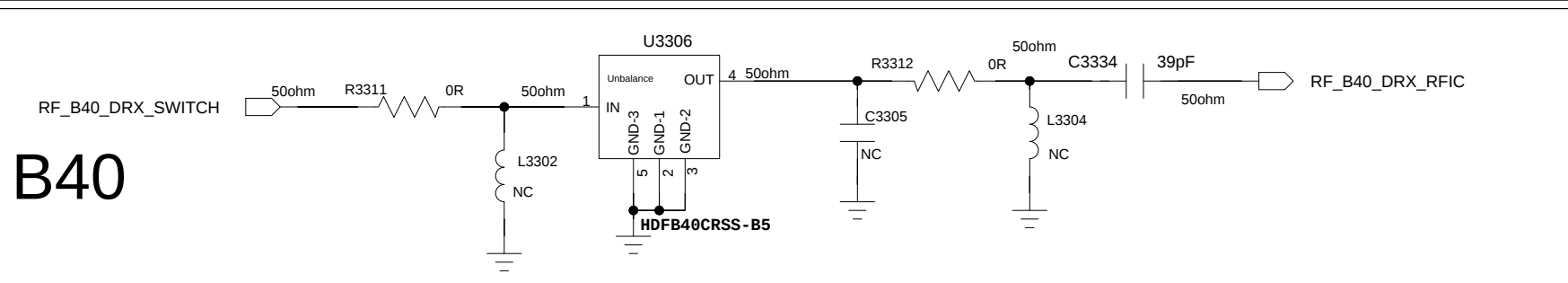


RF_MT6177M_RF_PRX

REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

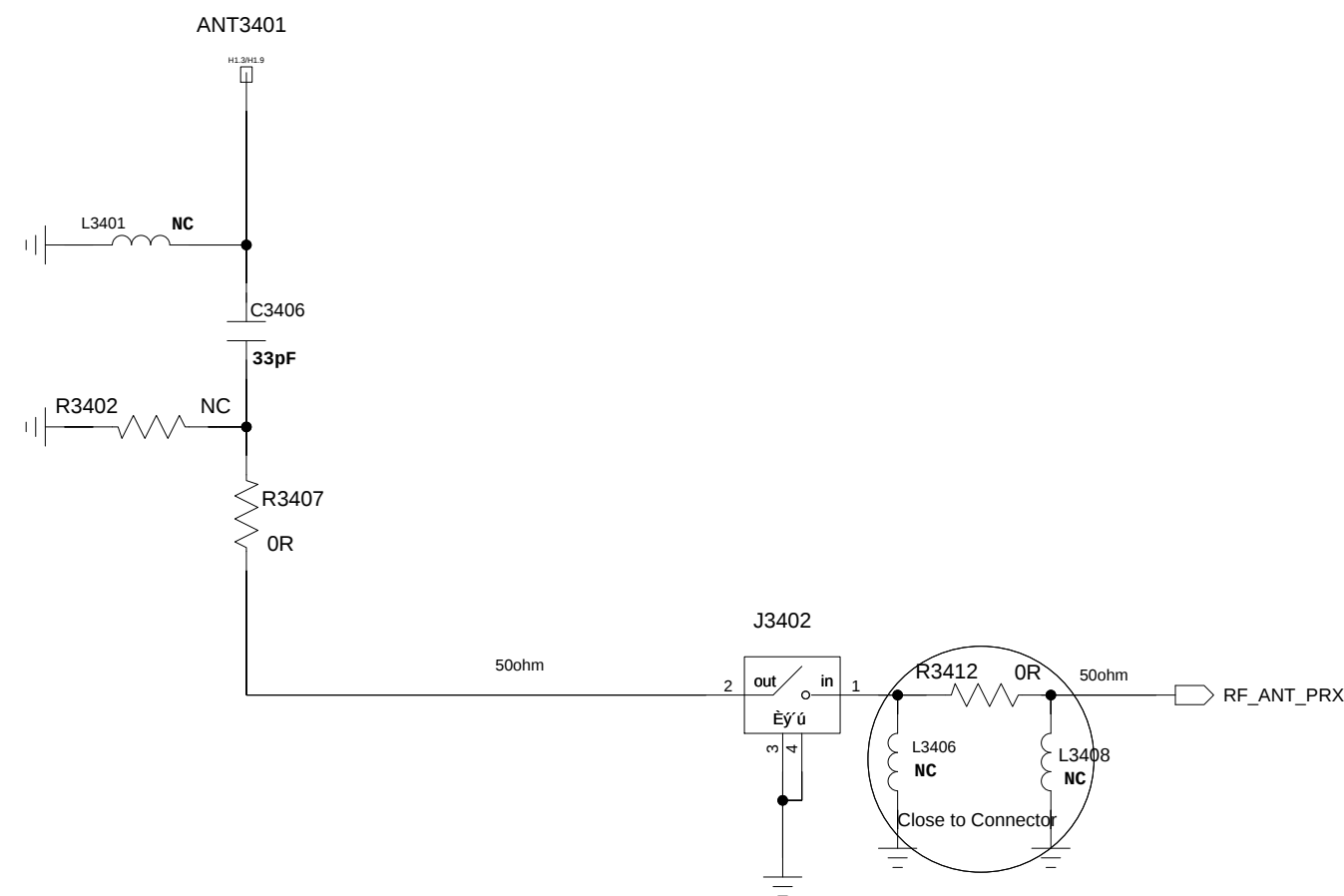


SP8T

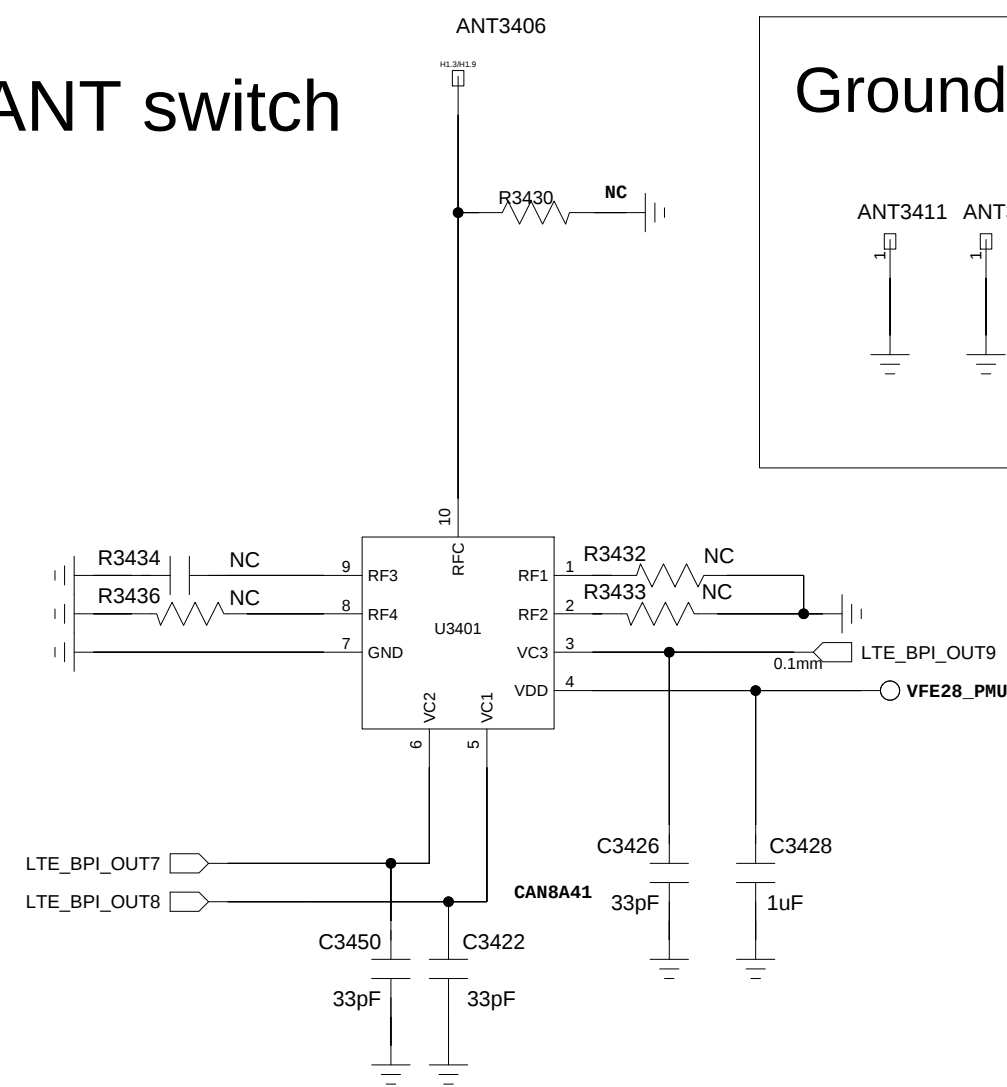


RF_MT6177M_RF_ANT

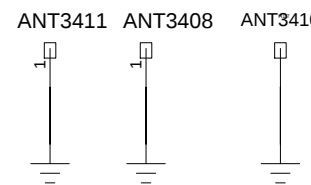
REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:



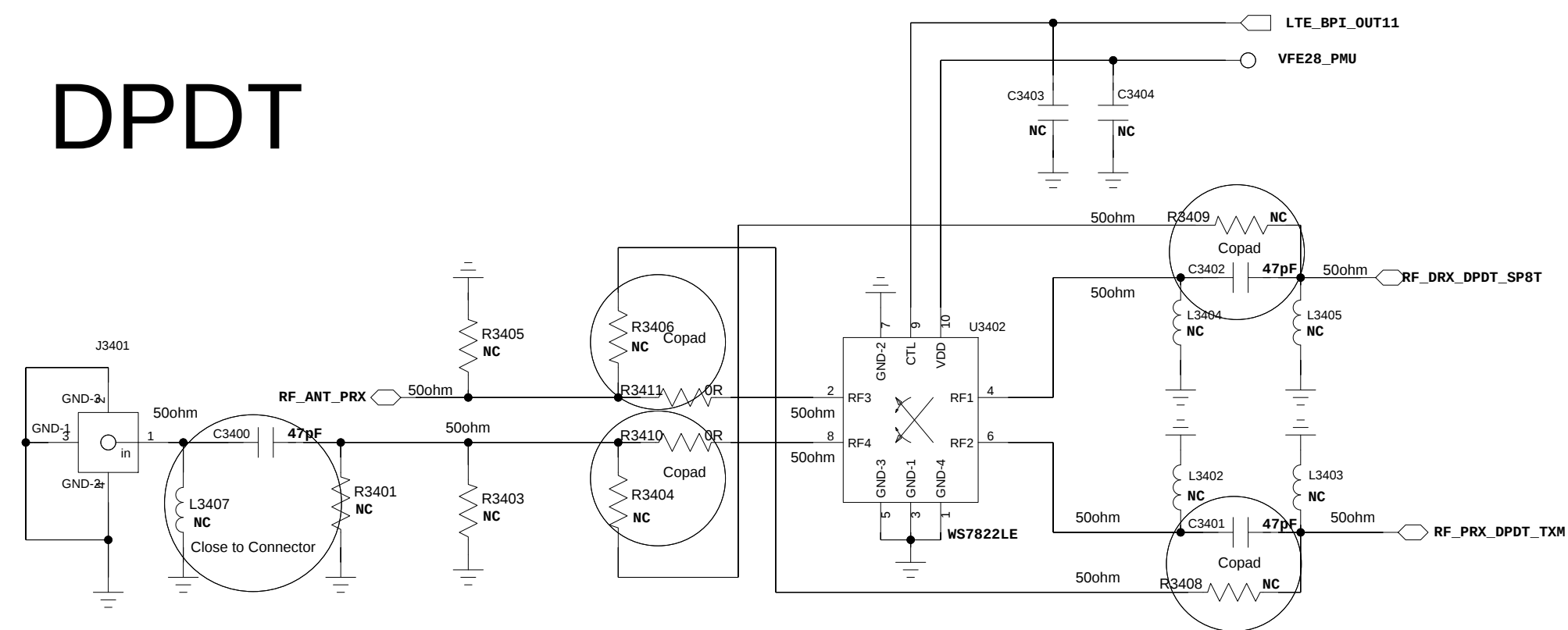
ANT switch



Ground Spring

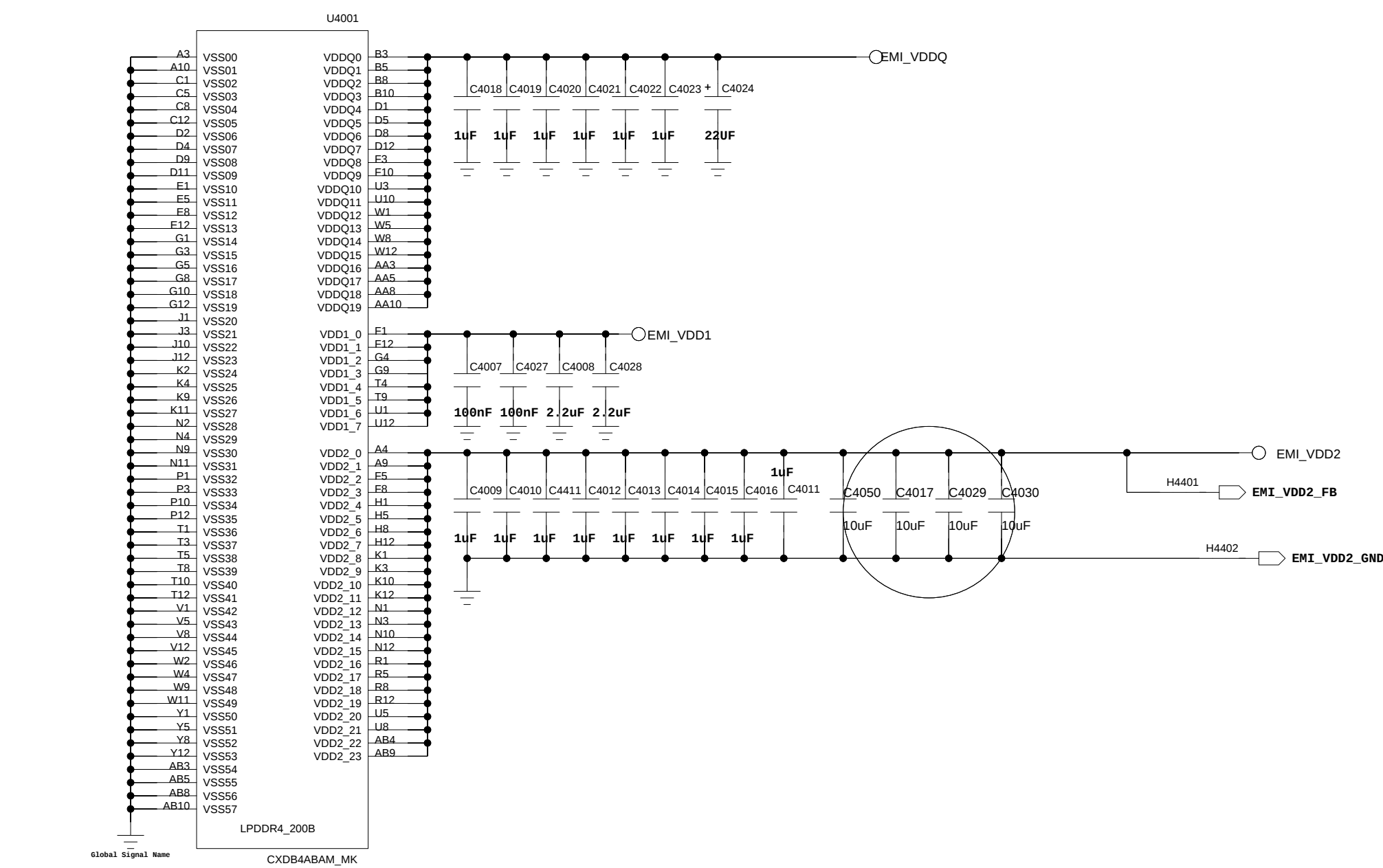
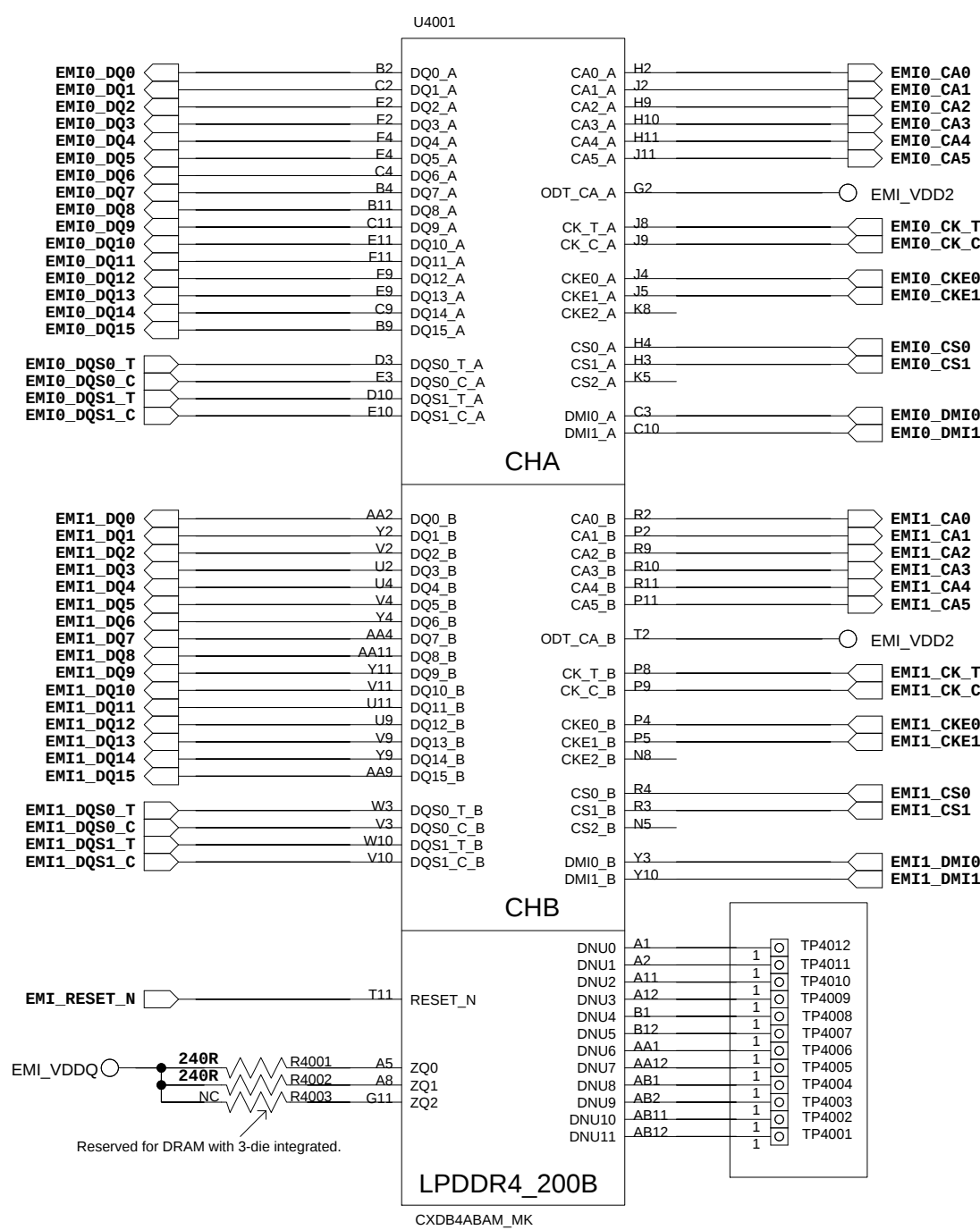
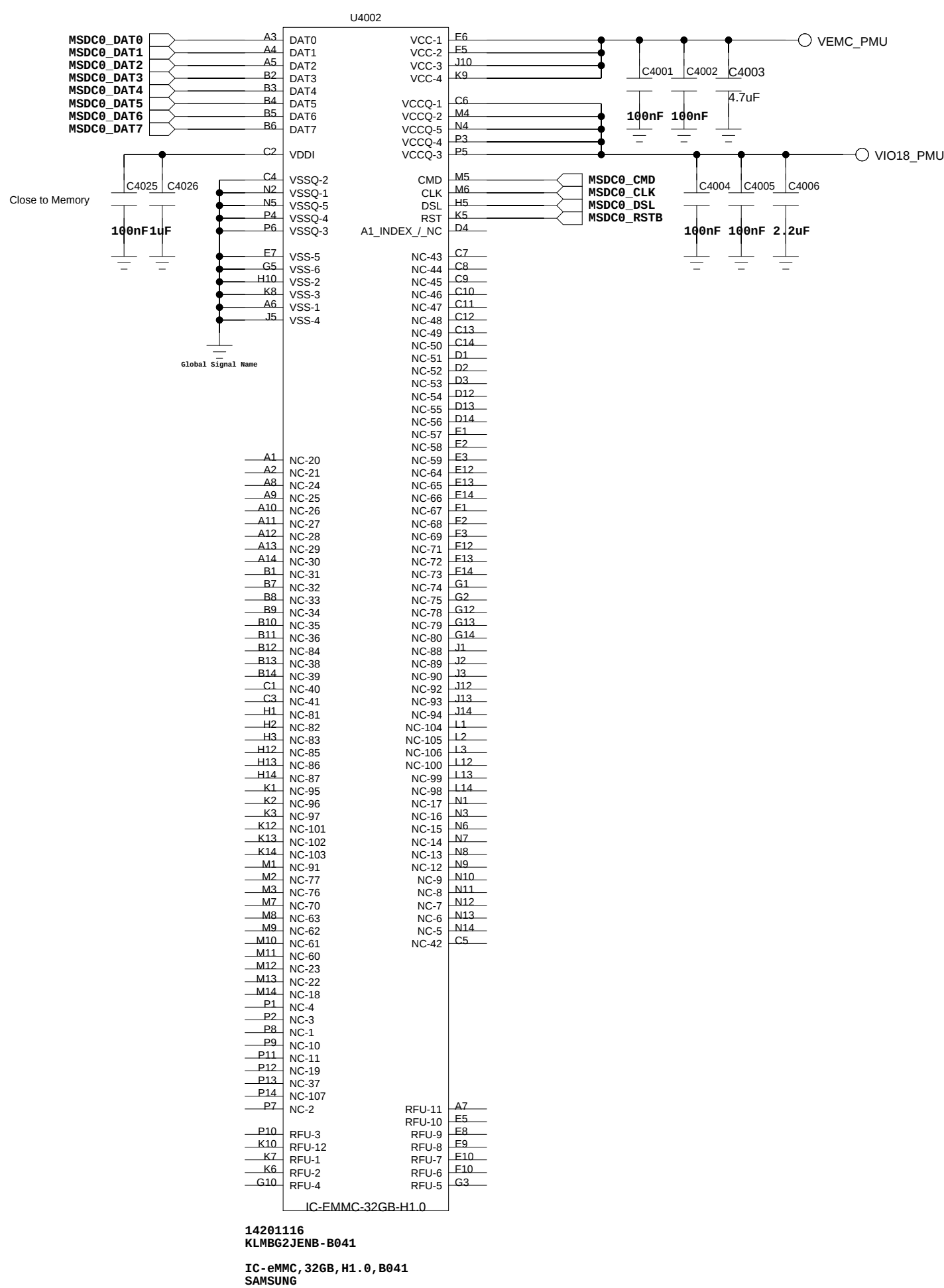


DPDT

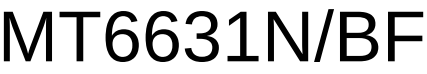


MEMORY_eMCP_LPDDR4X

REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:



REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:



Power domain

FM_AVDD28 0.2mm B5001 0R 0.25mm VCN28_PMU

C5019 1uF

AVDD18_GPS 0.2mm H5003 Star connection 0.25mm VCN18_PMU

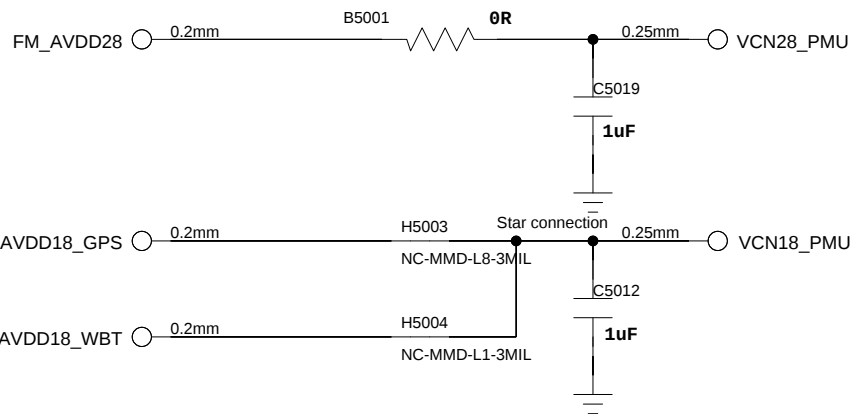
NC-MMD-L8-3MIL

C5012 1uF

AVDD18_WBT 0.2mm H5004 0.25mm

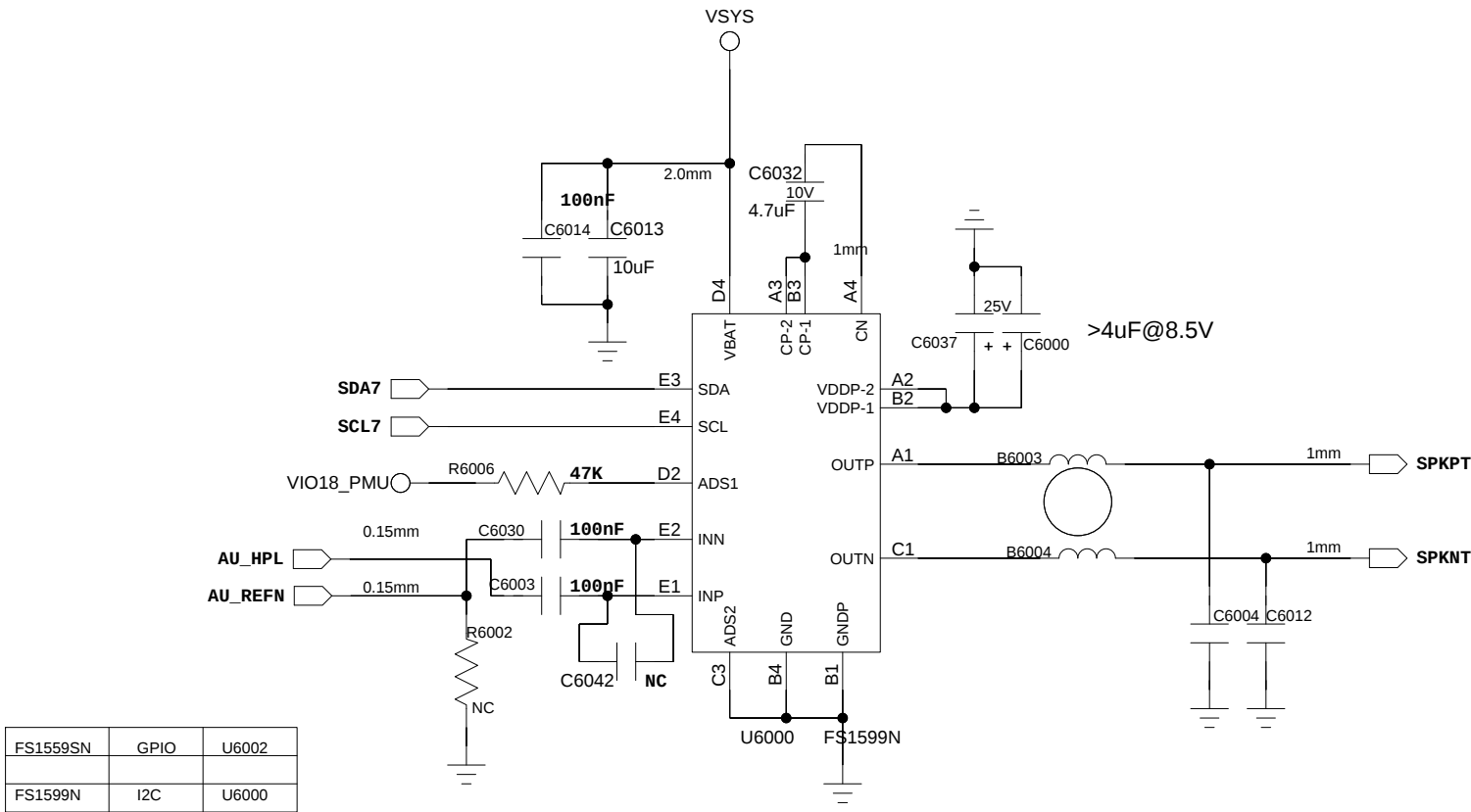
NC-MMD-L1-3MIL

Note: For MT6631 need to configure the VCN33_2_PMU to 2.8V by PMIC SW.



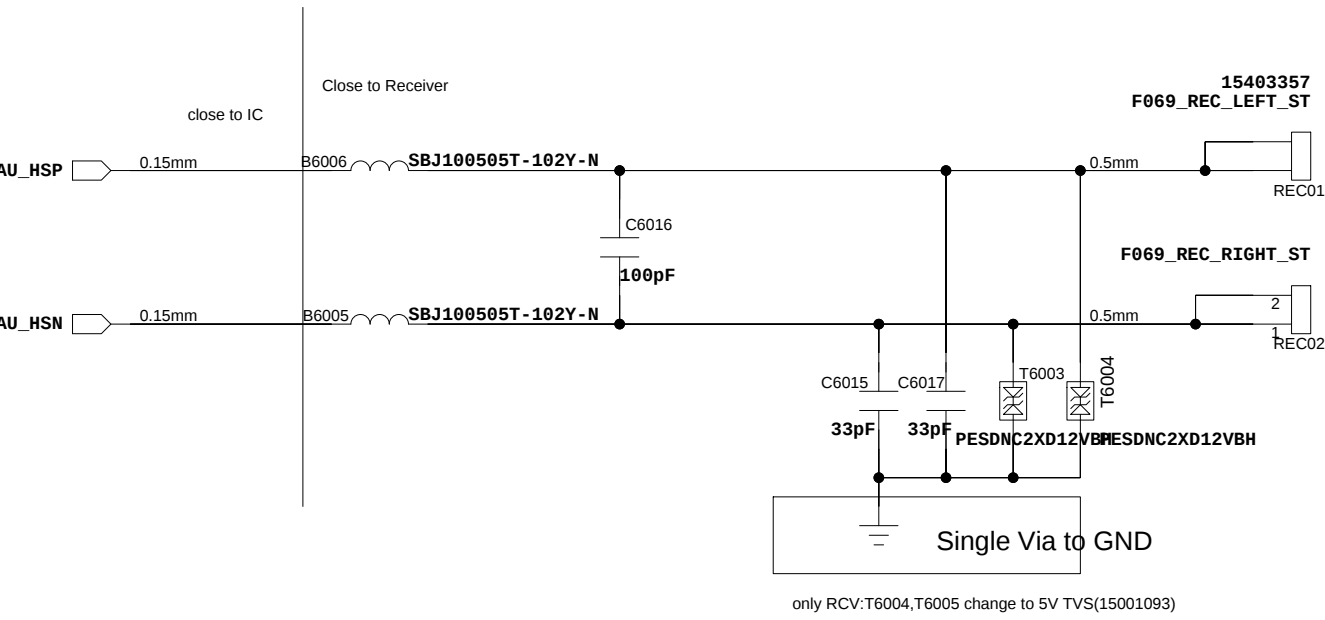
PERI_AUDIO_IO

Audio PA
UP SPK

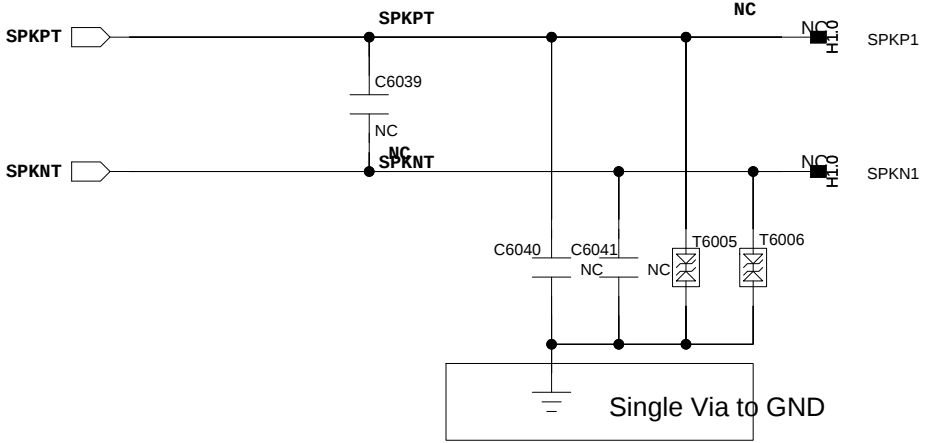


REC&SPK 2in1

RECEIVER



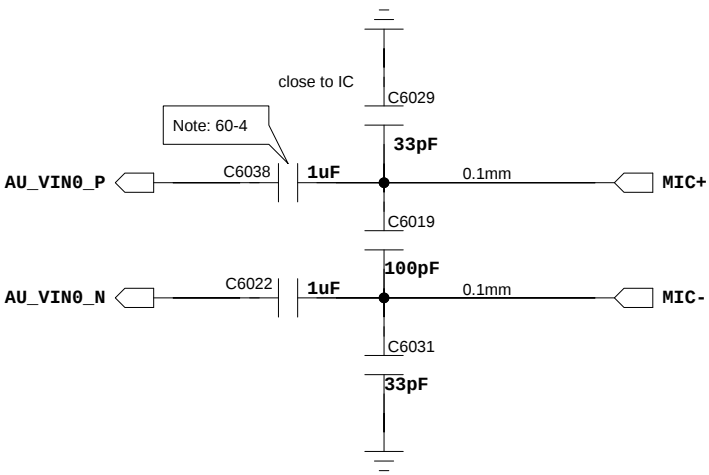
UP SPK



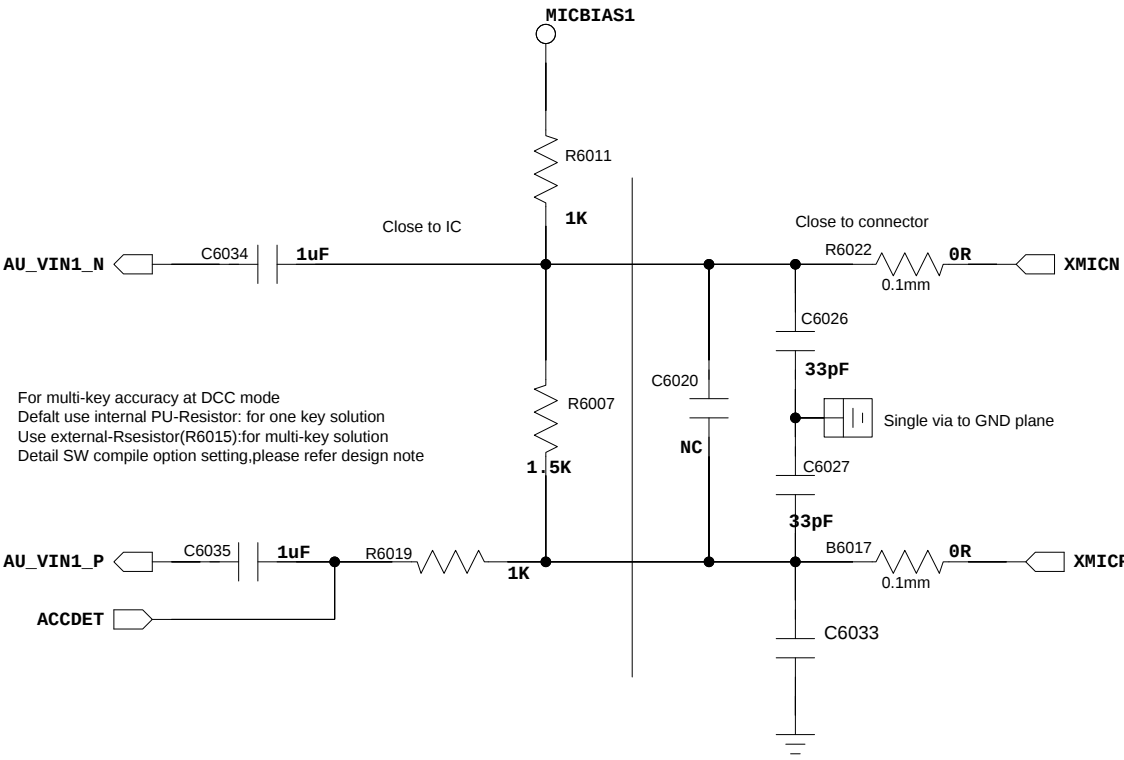
Audio PA
DOWN SPK

DOWN SPK ON SUB

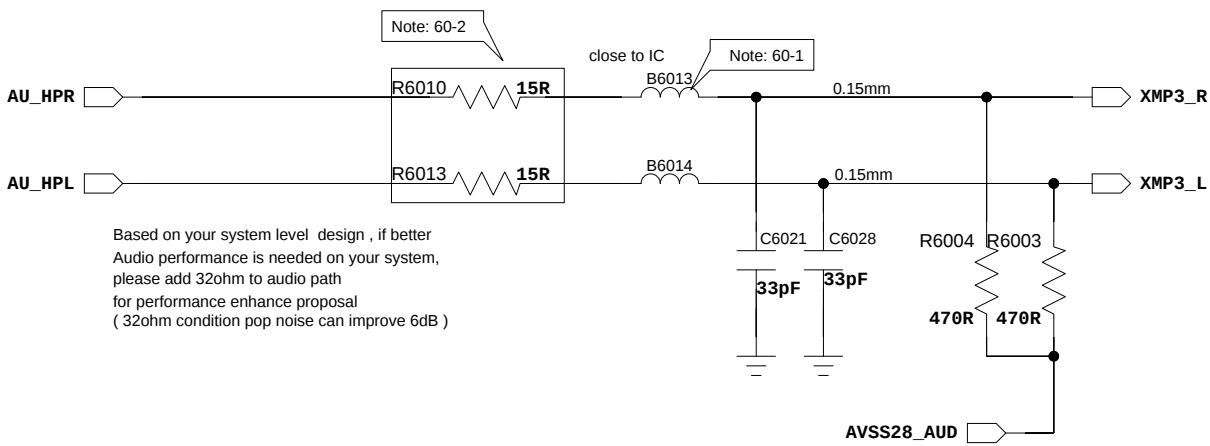
MAIN MIC



Earphone MICPHONE



Earphone Receiver



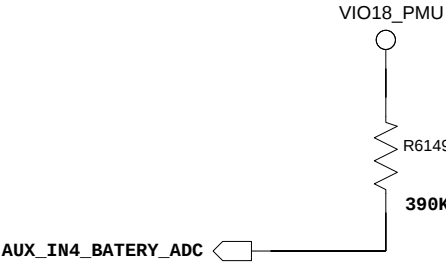
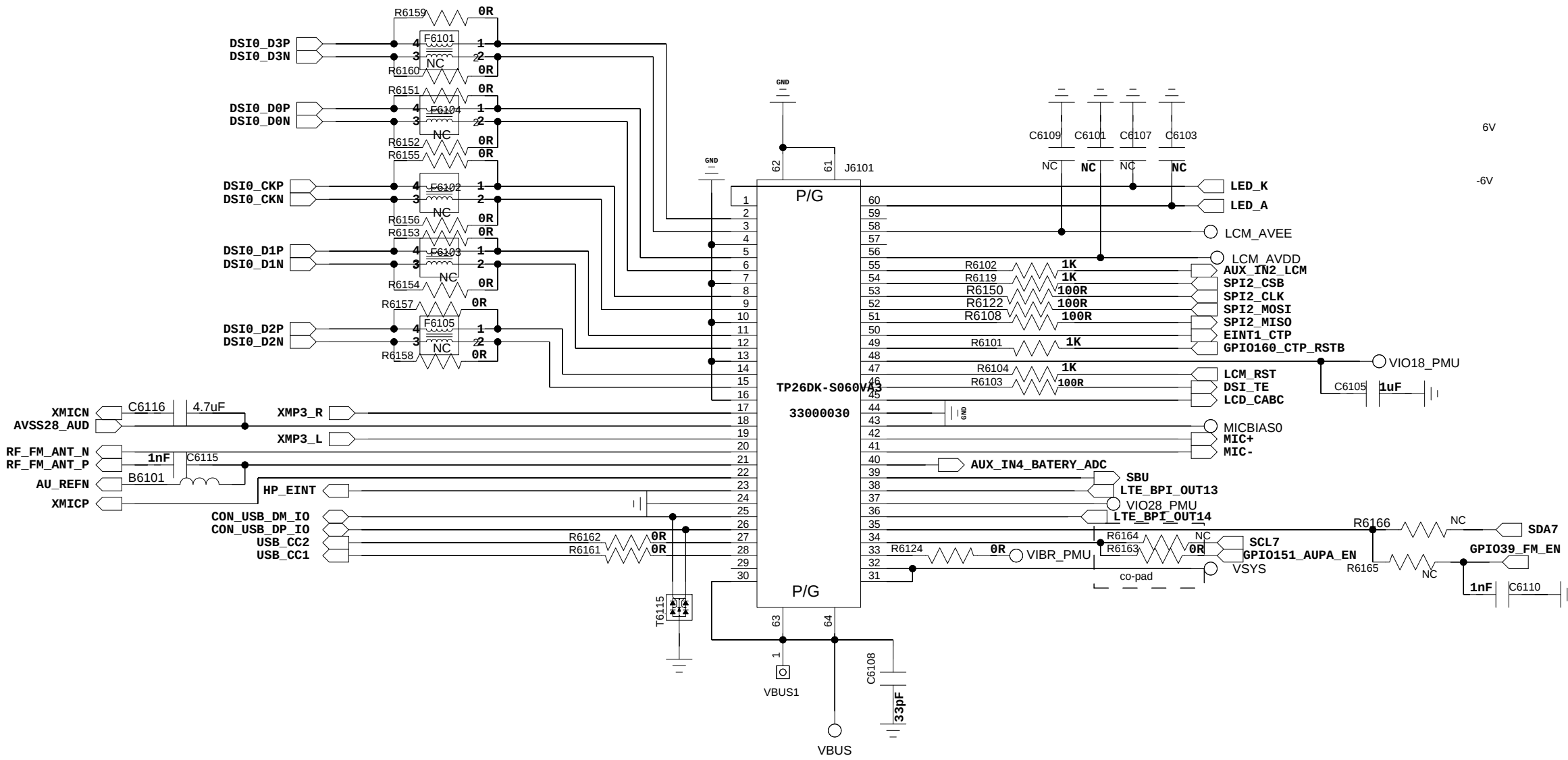
Schematic design notice of "60_PERI_AUDIO_IO" page.
Note 60-1: B6009 B6010 B6013 B6014 needs change to "BLM18BD102SN1" for high THD performance(-90dB), but this BOM change will result in FM RSSI 10dB degraded.
Note 60-2: To reserve a resistor in HPL and HPR in series connection both in order to optimize headphone pop noise. The recommended value of this resistor is 33R.
Note 60-3: Layout trace from MT6353 ball J3 AUDREFN to Audio jack GND must surround shield with GND.
Note 60-4: 0.1/1uF for ACC mode(1uF for WB_AMR Speech/0.1uF for NB_AMR Speech),0R for DCC mode.

PERI_LCM_CTP_FP

REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

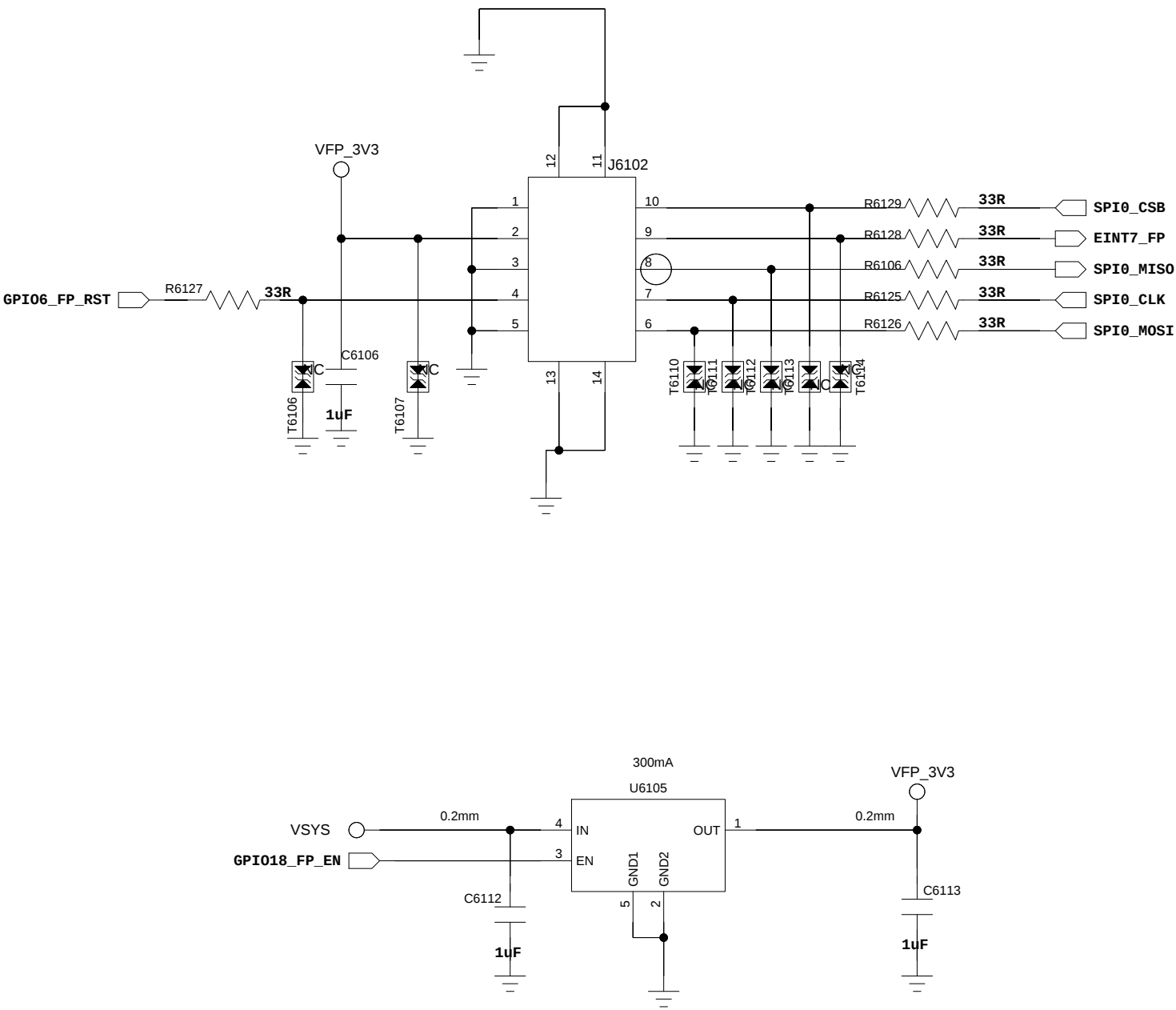
LCD_CTP_INTERFACE

CTP (NT36525) I2C address: 0X01 (Write:0x02, Read:0x03)



2. The distance is the shortest distance from package edge to edge.

FINGER PRINT

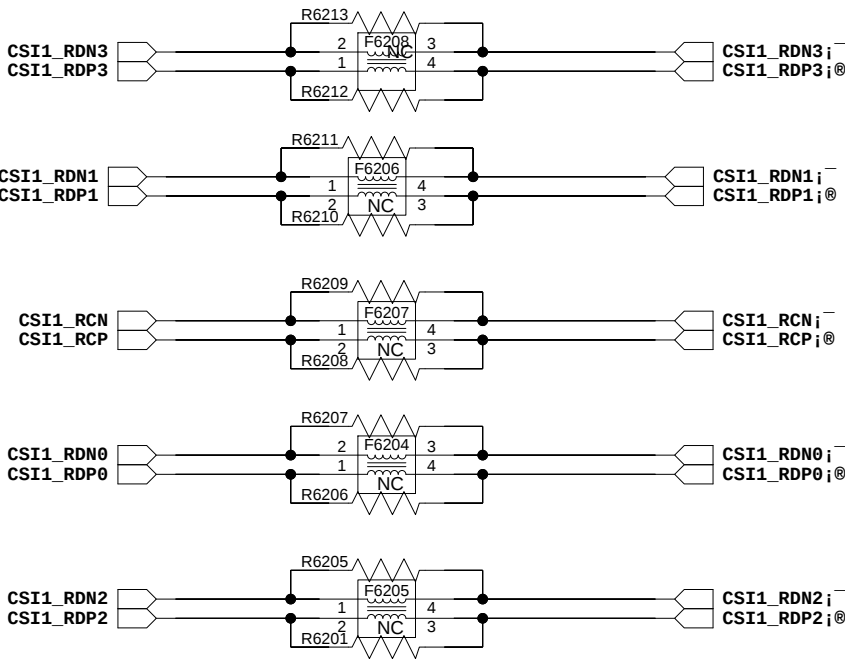
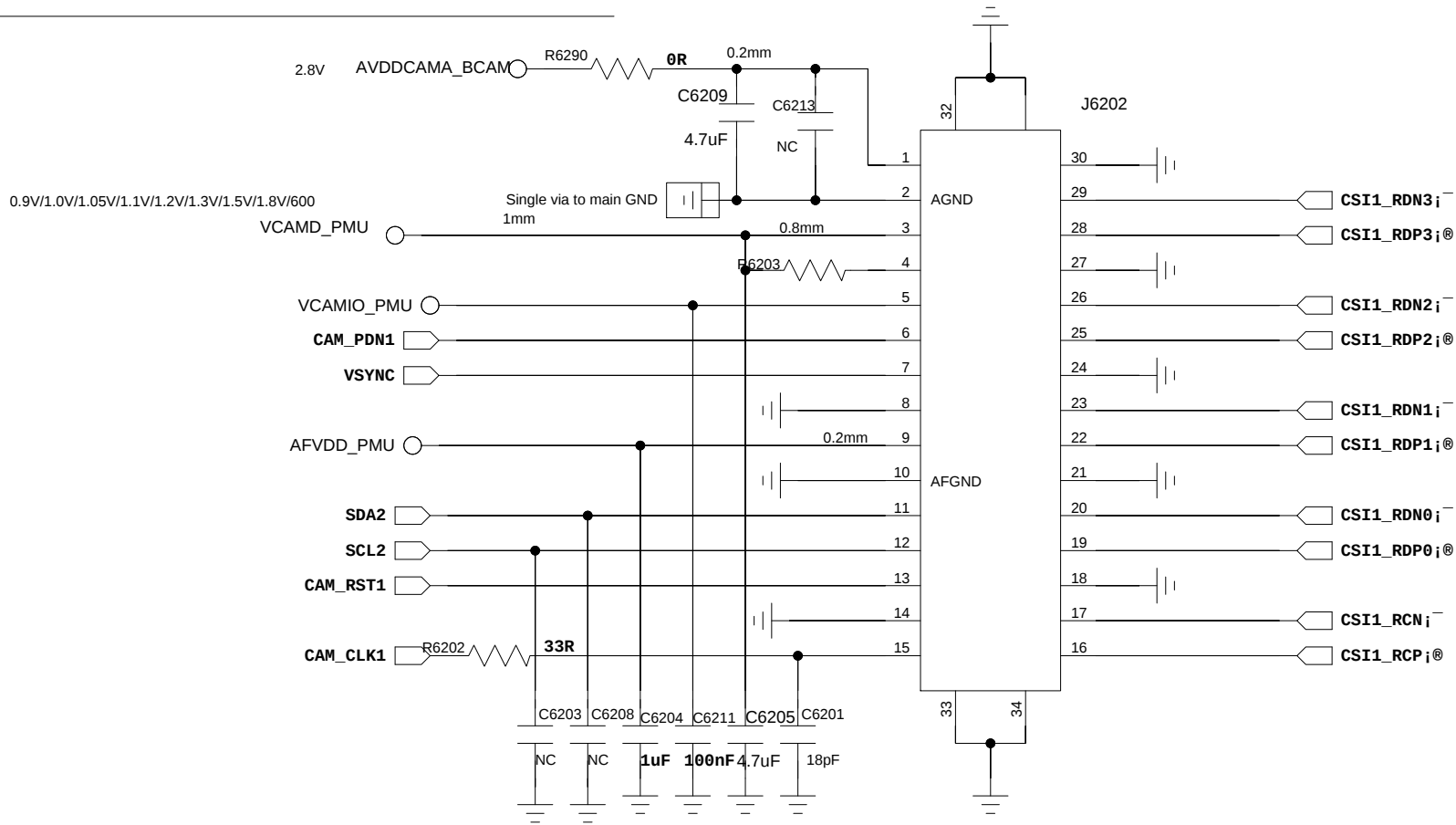


PERI_CAMERA_I

REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

REAR CAM I (50M/13M/8M)

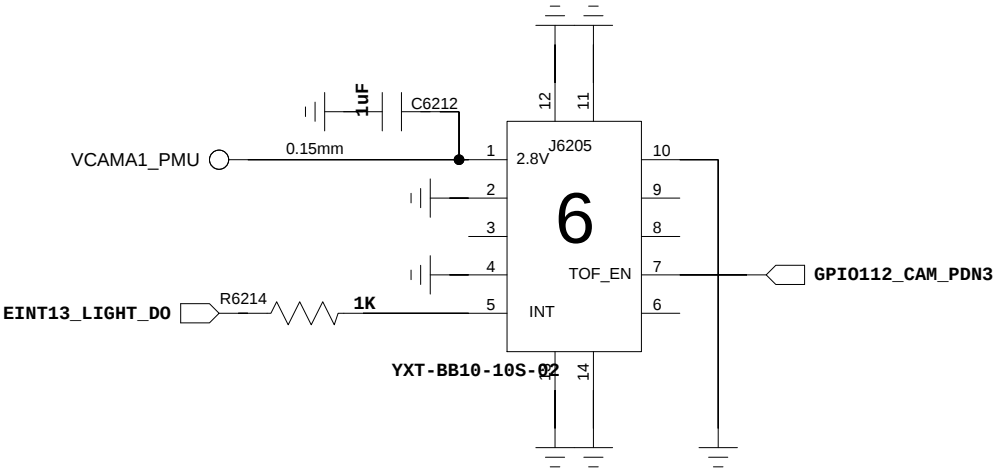
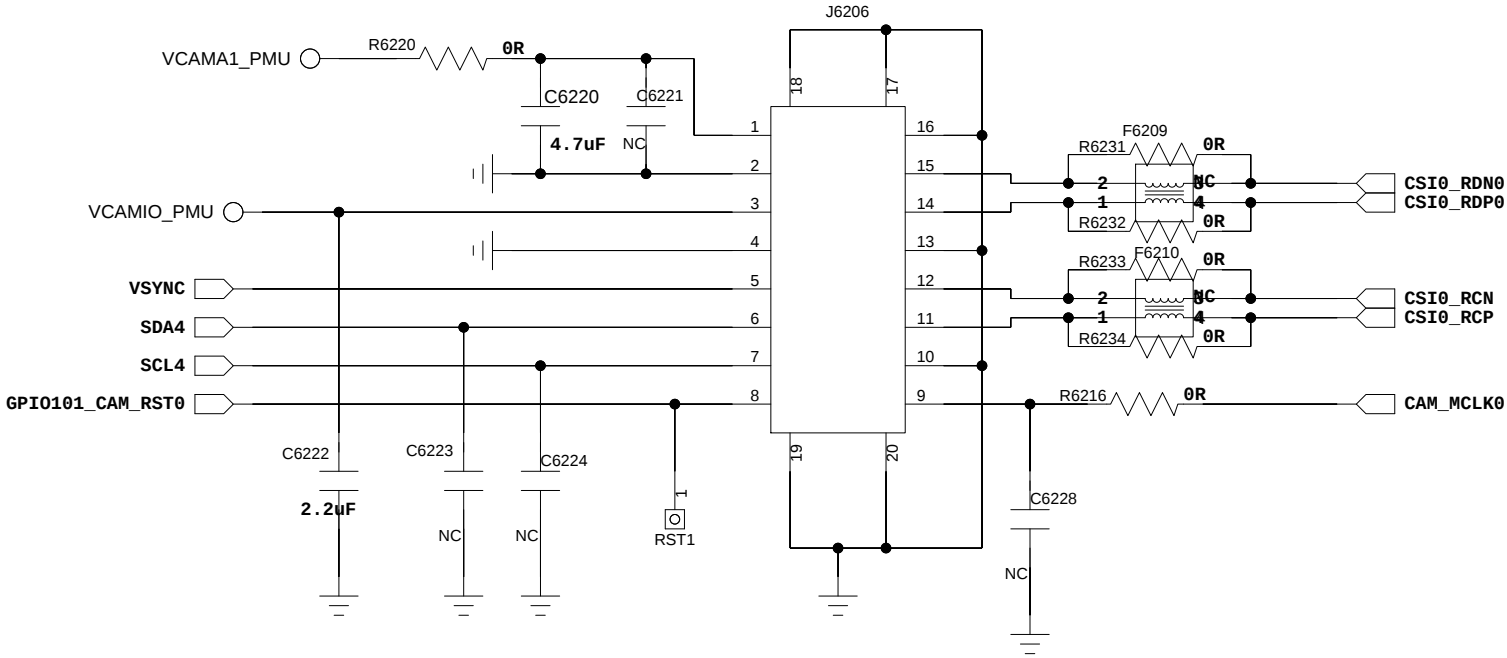
64M/50M/48M	R6203=0R
13M/16M/8M	R6203=NC



	SENSOR	I2C Address	VCAMA	VCAMD	VCAMIO	AFVDD	SAP
50M	HI-5021Q AA5021PXX	Write:0x40 Read:0x41	2.8V @78mA	1.1V @598mA	1.8V@ 31mA	2.8V@ 103mA	17201826(0.7um)
	SSKJN1SQ03-FGX9	Write:0x20 Read:0x21	2.8V @67.7mA	1.05V @260.7mA	1.8V@ 4mA	2.8V@ 100mA	17201711(0.64um)
13M	HI-1336-AA1336NXX-C20AHX	Write:0x40 Read:0x41	2.8V @44mA	1.1V @106mA	1.8V@ 6mA	2.8V@ 125mA	17201835
	SSK3L6X03-FGX	Write:0x20Read:0x21	2.8V @45mA	1.05V @160mA	1.8V@ 1.1mA	2.8V@ 125mA	17201836
8M	HI-846-AA0846NXX-B2CWCX	Write:0x40 Read:0x41	2.8V @42mA	1.2V @67mA	1.8V@ 2mA	2.8V@ 123mA	17201833
	GC08A3-WA1XA	Write:0x62Read:0x63	2.8V @60mA	1.2V @150mA	1.8V@ 10mA	2.8V@ 125mA	17201834

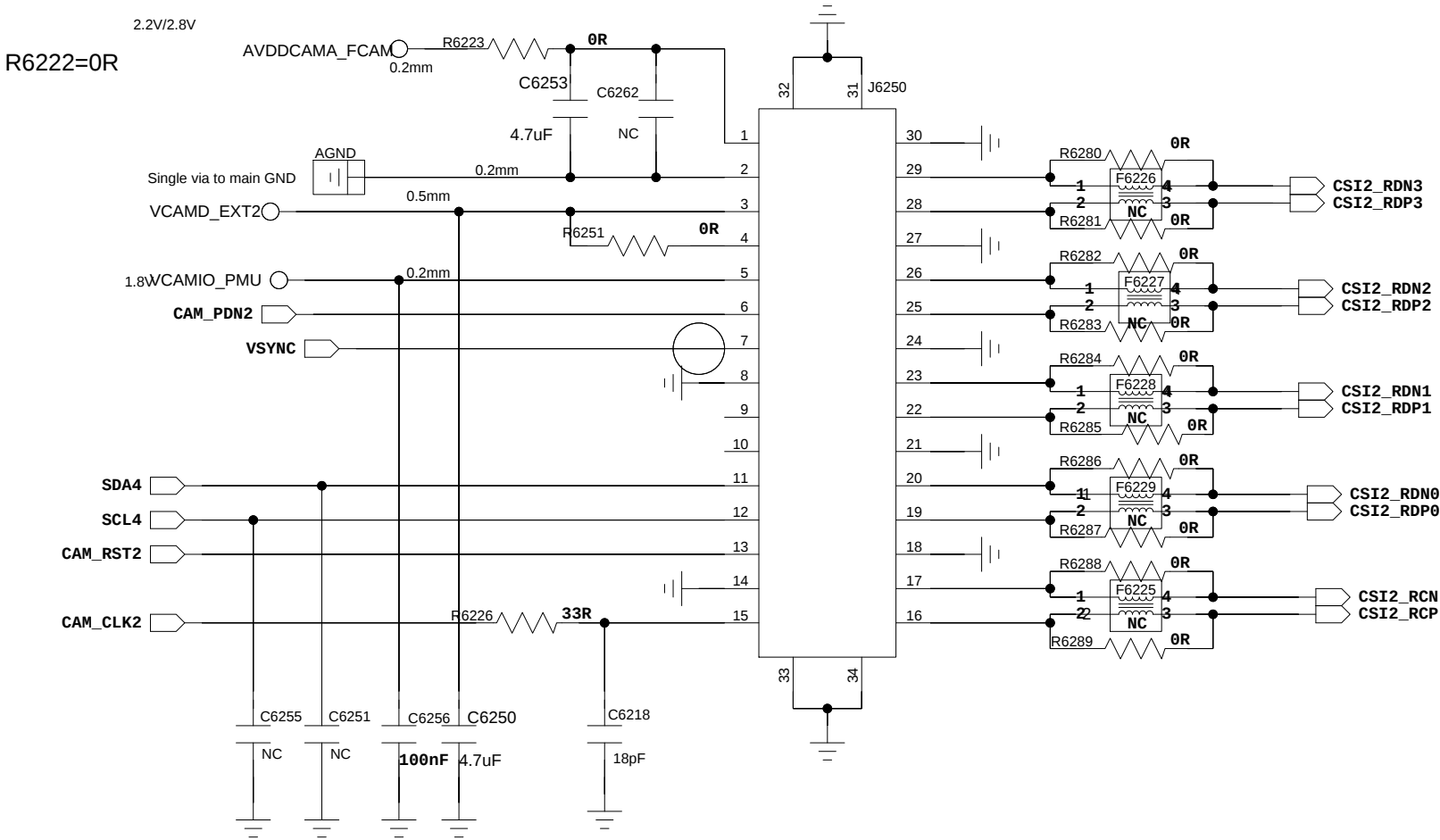
REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

2M



Front Camera (32M/16M/8M/5M)

32M	R6251=0R R6222=NC VCAMD_EXT1 ¹ @μç
5M/16M/8M	R6251=NC

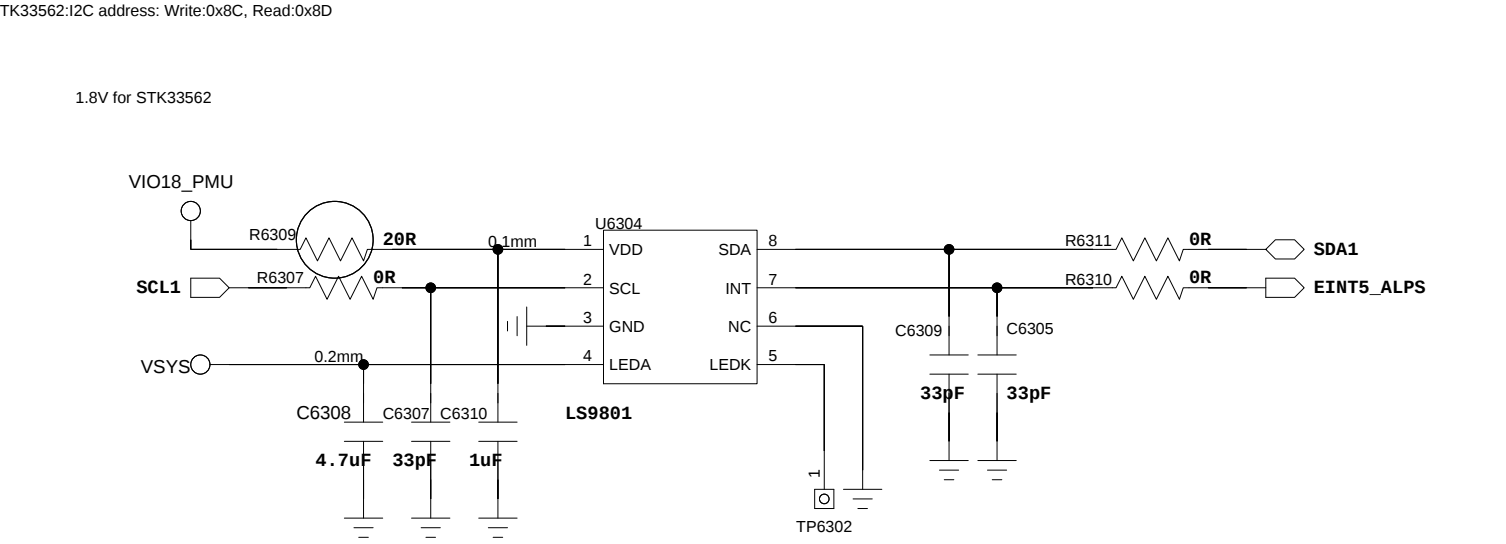


	SENSOR	I2C Address	VCAMA	VCAMD	VCAMIO	SAP
32M	GC32E1-WA1XA	Write:0x94 Read:0x95	2.8V 43mA	1.2V 93.05mA	1.8V 4mA	
16M	HI-1631Q	Write:0x40 Read:0x41	2.8V 49mA	1.1V 115mA	1.8V 3mA	17201821
8M	GC8034-WC1X0	Write:0x6E Read:0x6F	2.8V 35mA	1.25V 140mA	1.8V 10mA	17201857
	GC08A3-MDD0	Write:0x24 Read:0x25	2.8V 60mA	1.2V 150mA	1.8V 10mA	17201829
	OV08856-GA4A-2	Write:0x6C Read:0x6D	2.8V 28mA	1.2V 95mA	1.8V 2.7mA	17201831
5M	GC5035-MCHDQ	0X6E(W)/0X6F(R)	2.8V 35mA	1.2V 80mA	1.8V 3mA	
	HI-556D(HYNIK)	0X50(W)/0X51(R)	2.8V 43mA	1.2V 46mA	1.8V 1mA	

PERI_SENSORS

REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

AL& PS Sensor

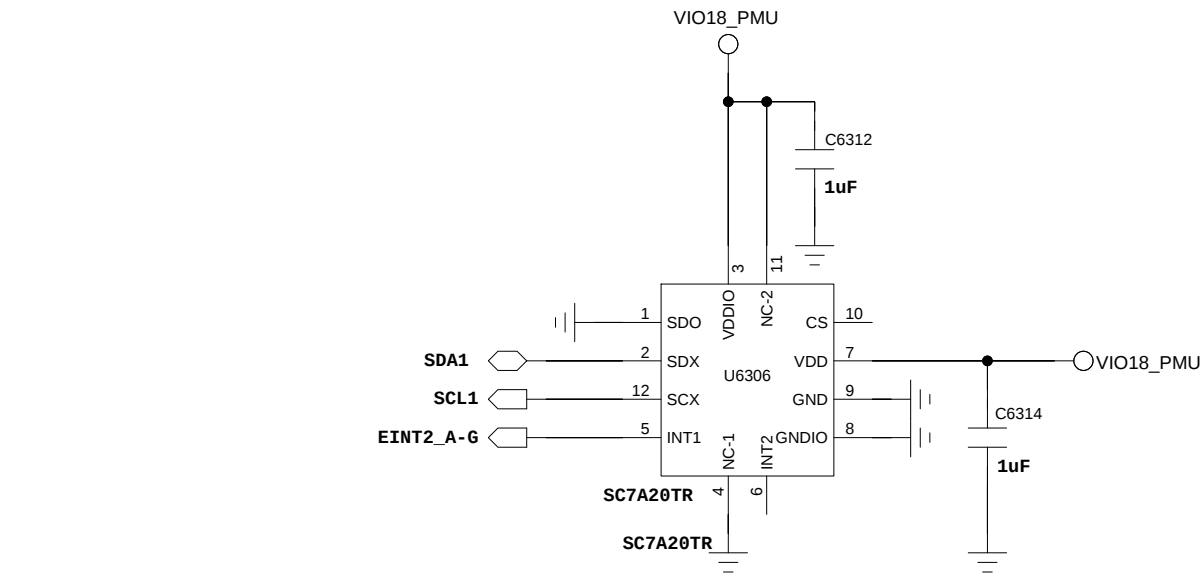


G-Sensor

MXC6655XA:ADDRESS:0x2A(Write)/0x2B(Read)

SC7A20:ADDRESS:0x30(Write)/0x31(Read)

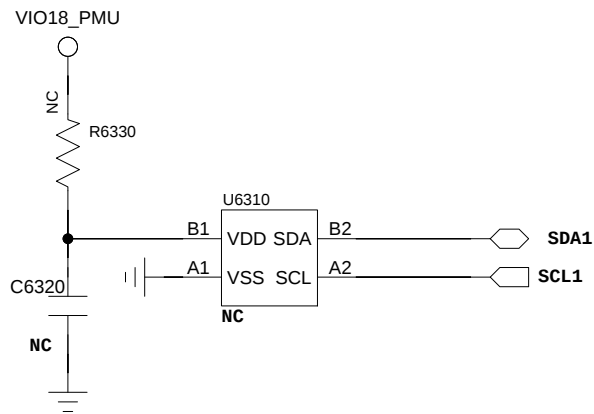
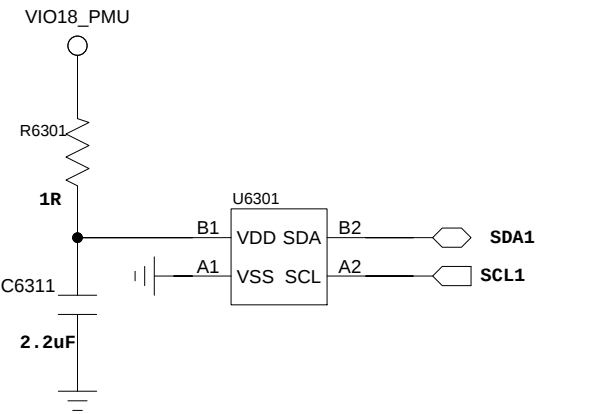
MXC4005XC:ADDRESS:0x2A(Write)/0x2B(Read)



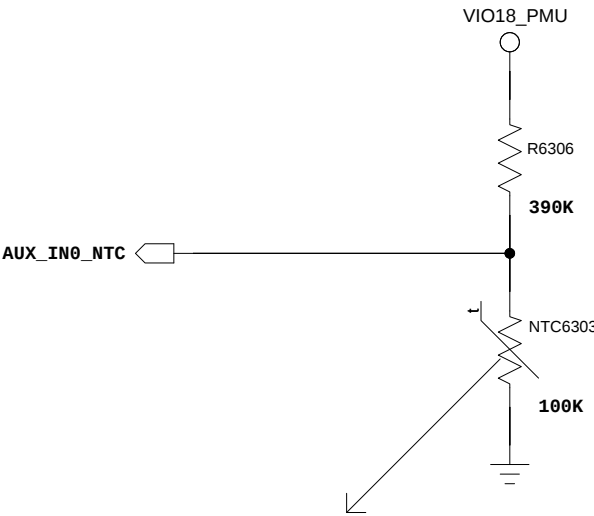
M-Sensor(COMPASS)

MMC5603:I2C ADDRESS:0x60(Write)/0x61(Read)

QMC6308:I2C ADDRESS:0x58(Write)/0x59(Read)



Thermistor to sense AP temperature



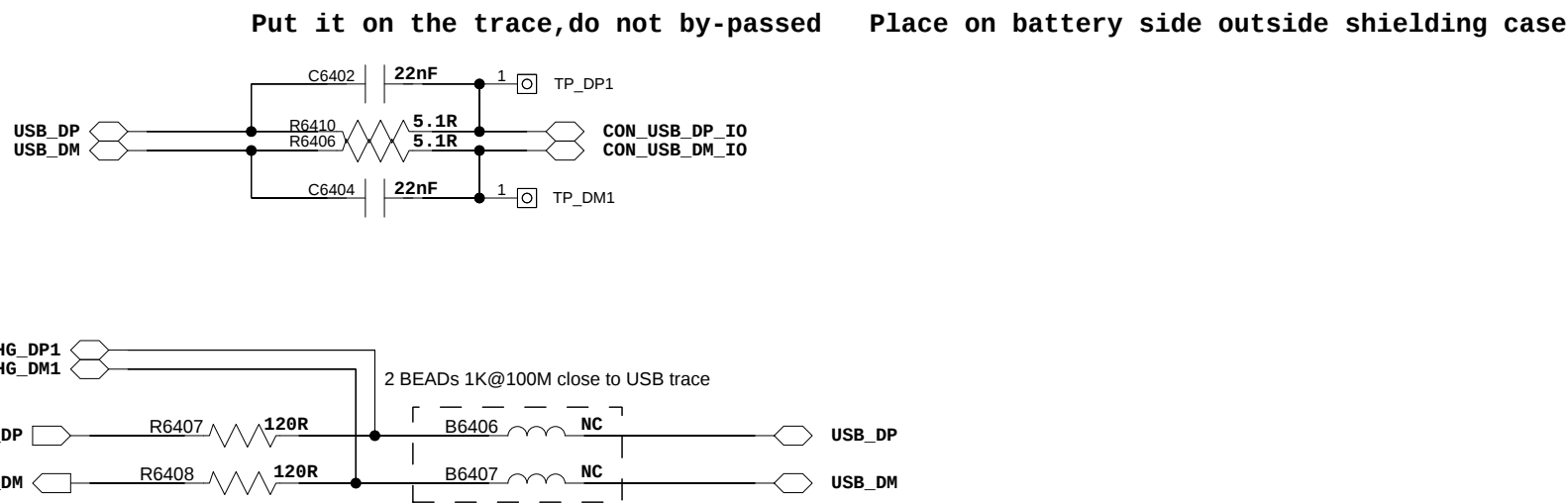
1. NTC6303must keep a distance about 68 mm away from BB and far from other heat sources 10 mm at least.
2. The distance is the shortest distance from package edge to edge.

component	MXC6655XA	SC7A20	STK8BA50-S
C6302	NC	100nF	1uF
C6303	1uF	100nF	1uF

PERI_EXCH_IO

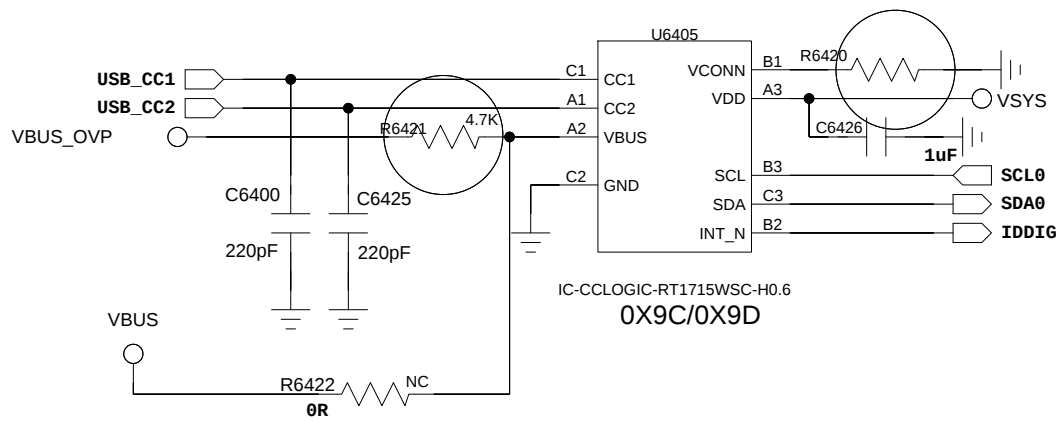
REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

RFC

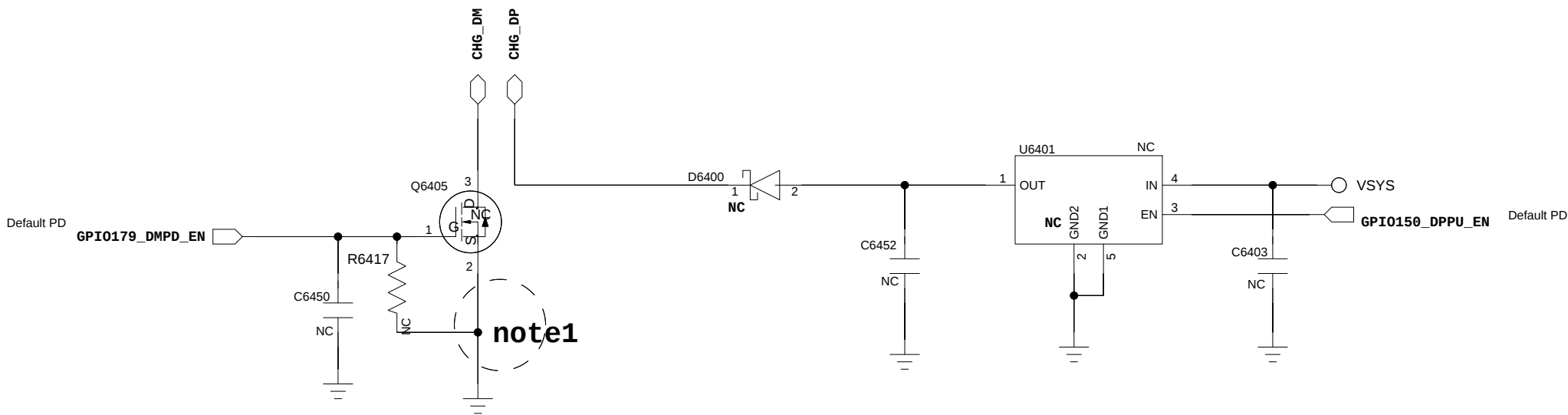


18W IC	T6405	R6407	R6408	
OTHERS	RES-->0R	120R	120R	T6405 SMT 0R

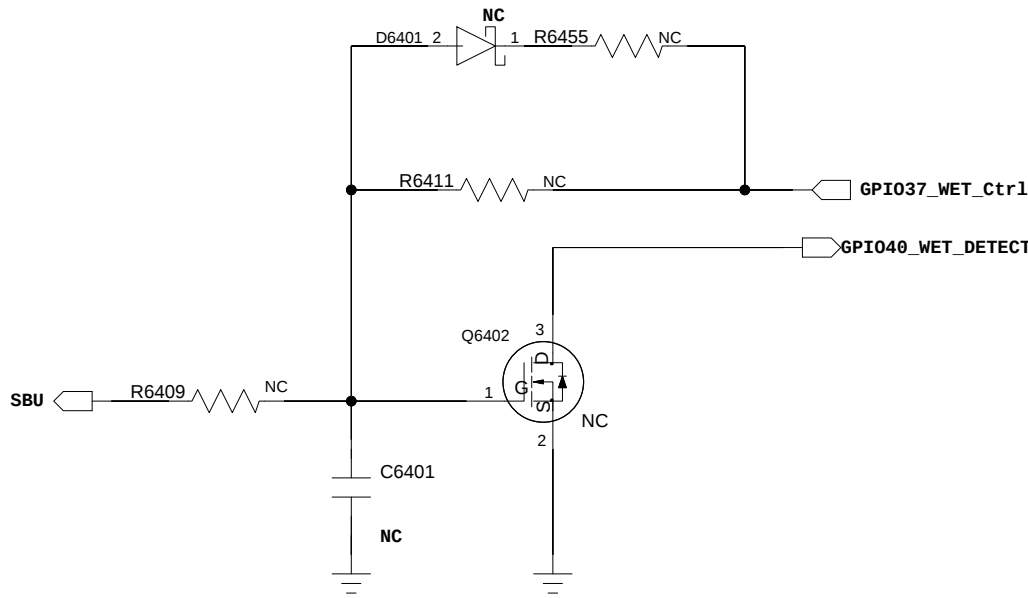
CC Logic



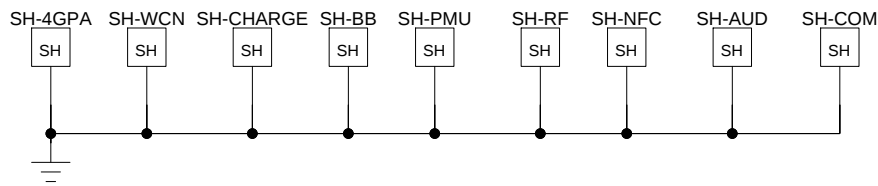
HVDCP TA



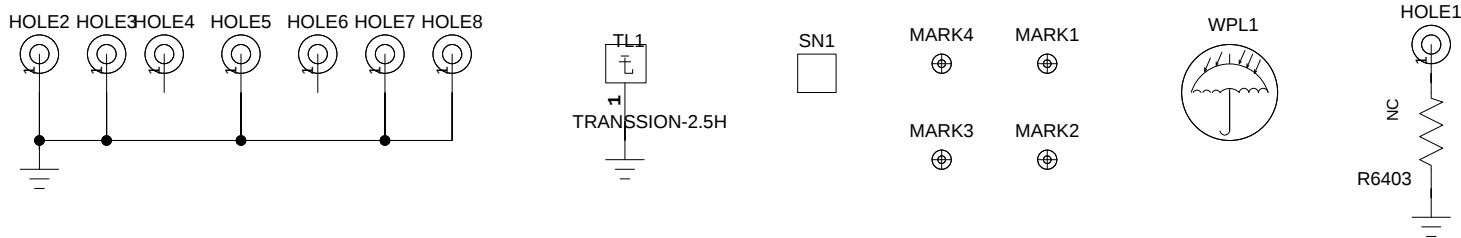
WET detect



SHIELDING



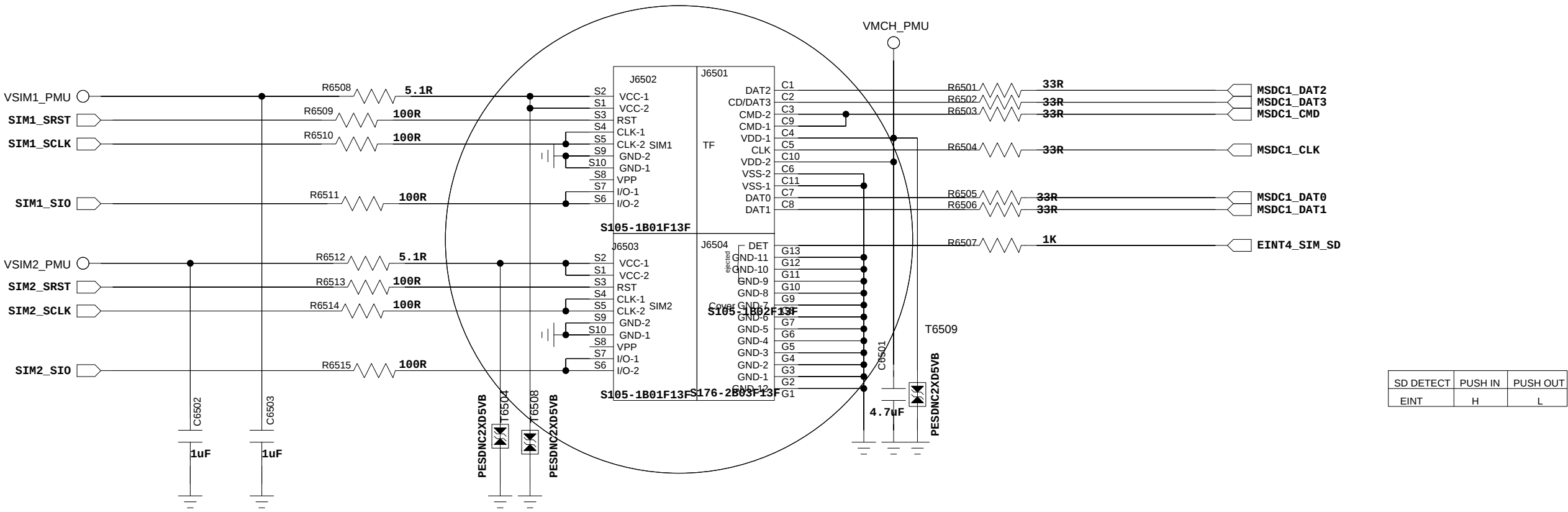
LOGO&SN&MARK



PERI_SIM_SD_KEYPAD

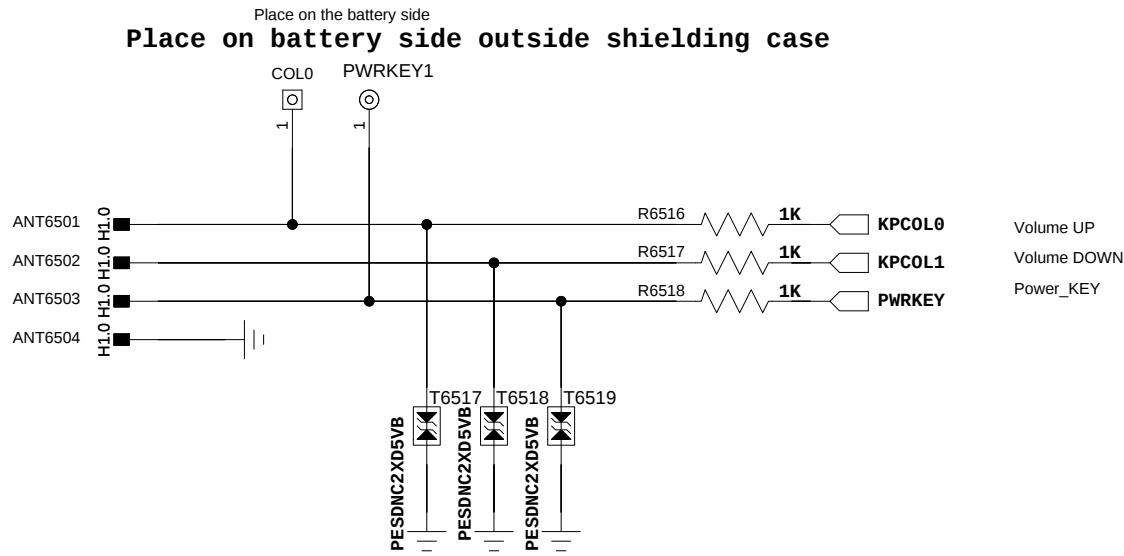
REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

SIM1/2-SD-CARD



SD POWER CONTROL

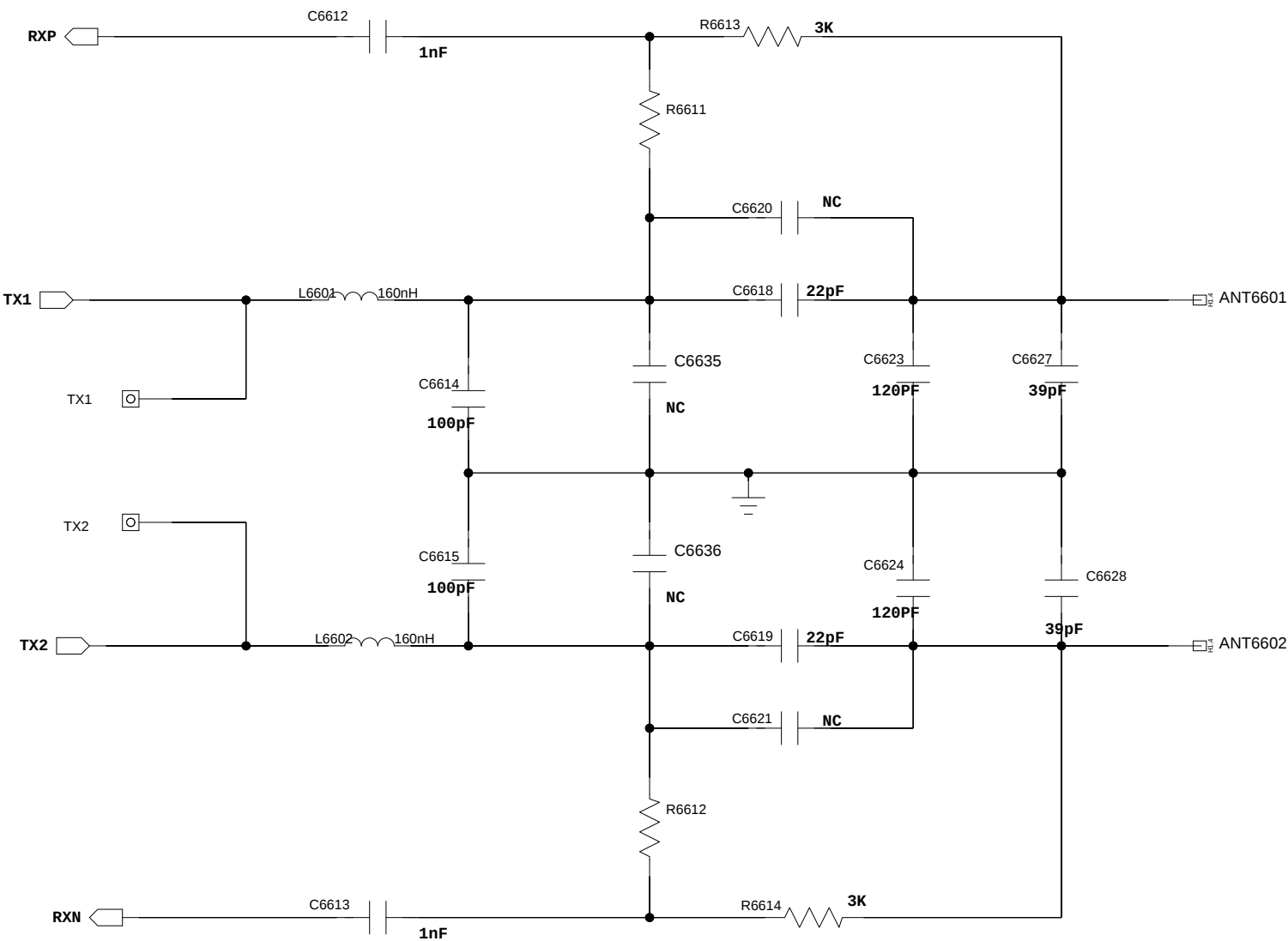
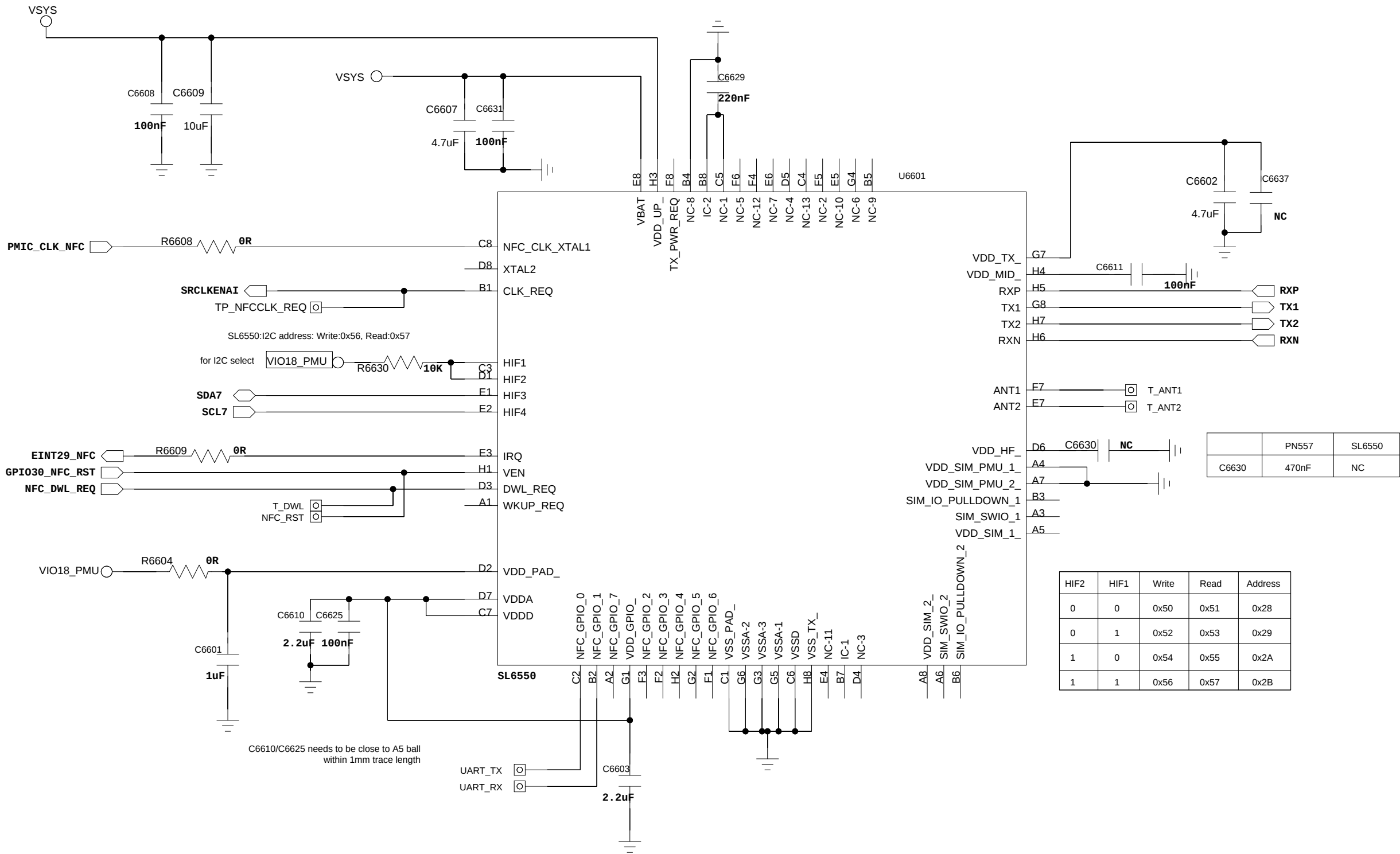
SIDEKEY



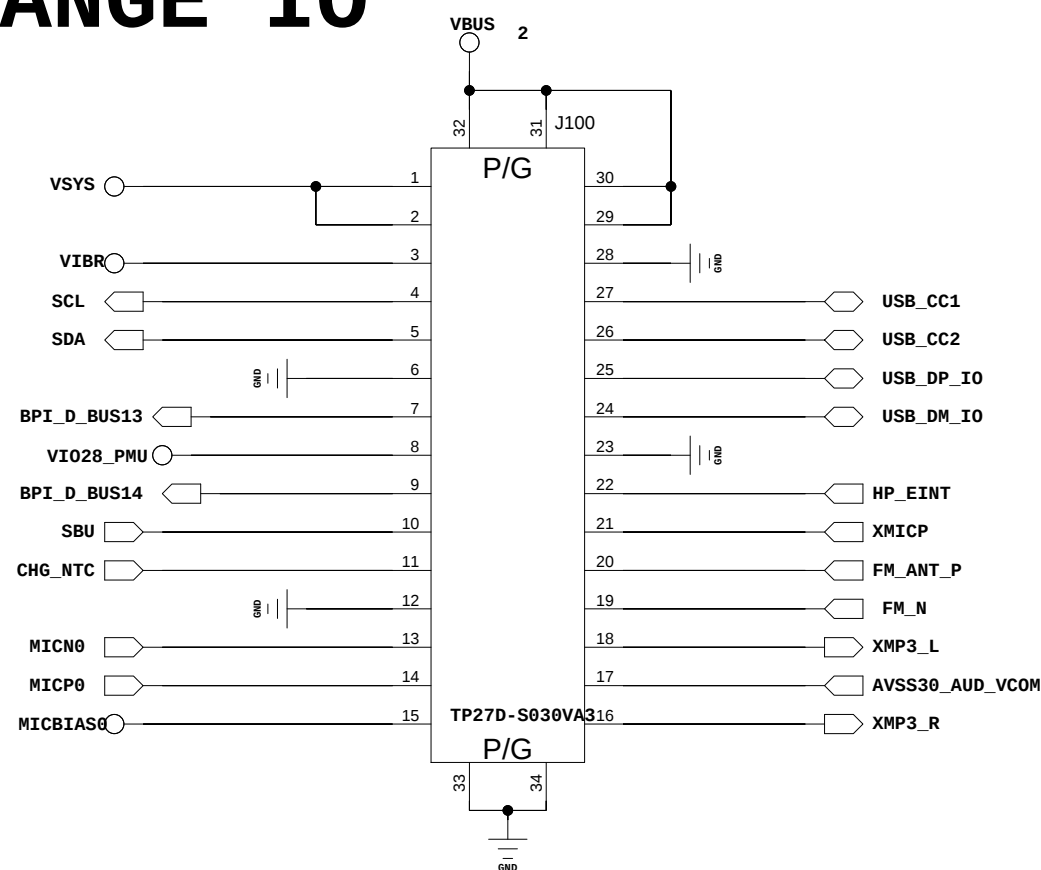
PERI_NFC

REVISION RECORD			
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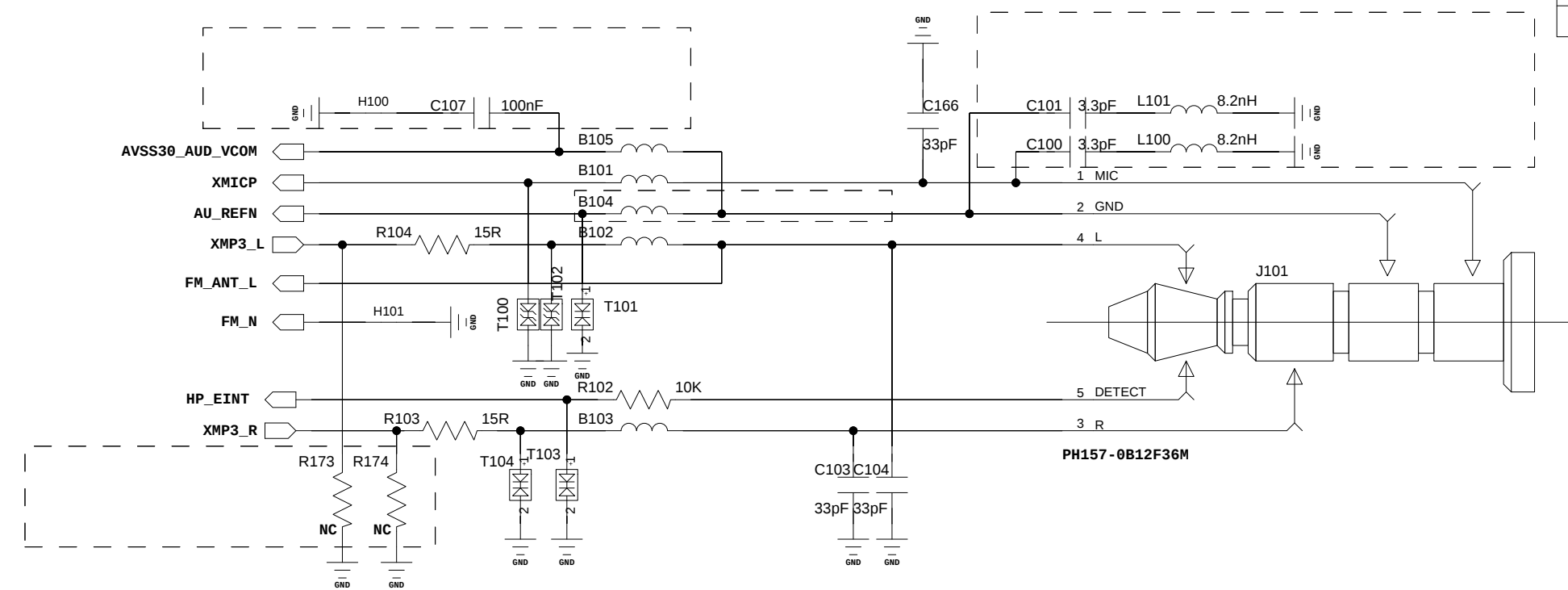
NC



EXCHANGE IO

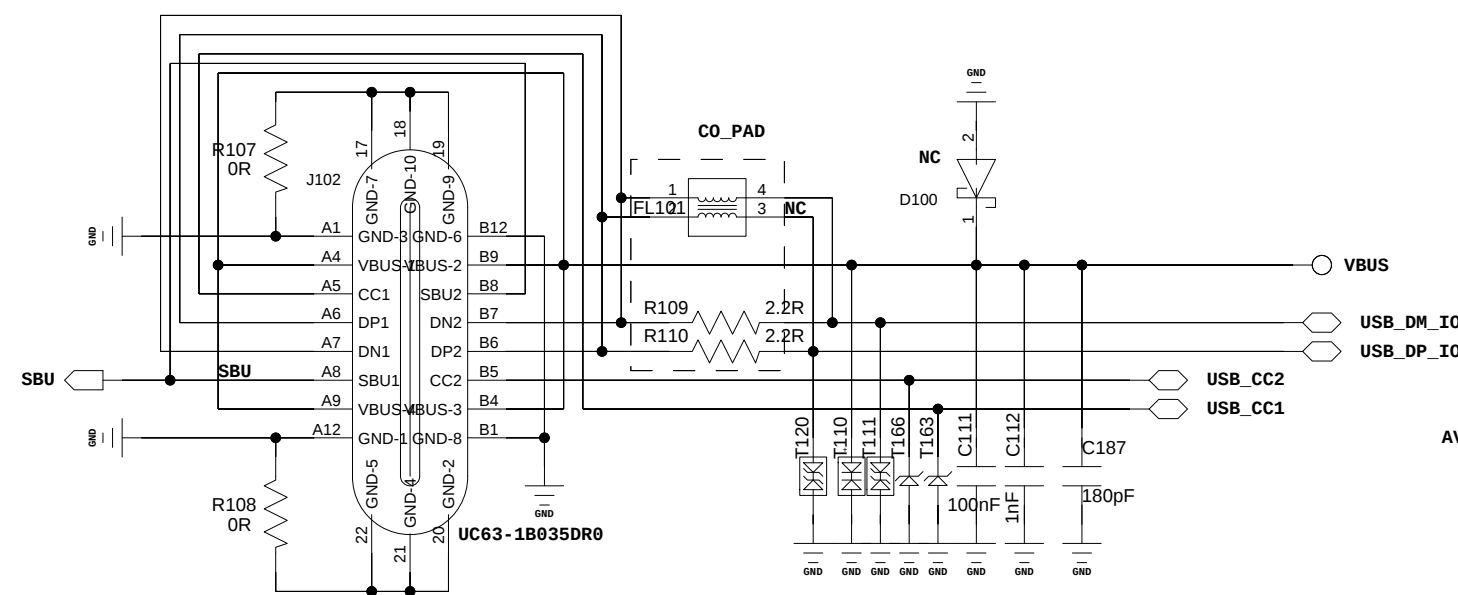


AUDIO EAR

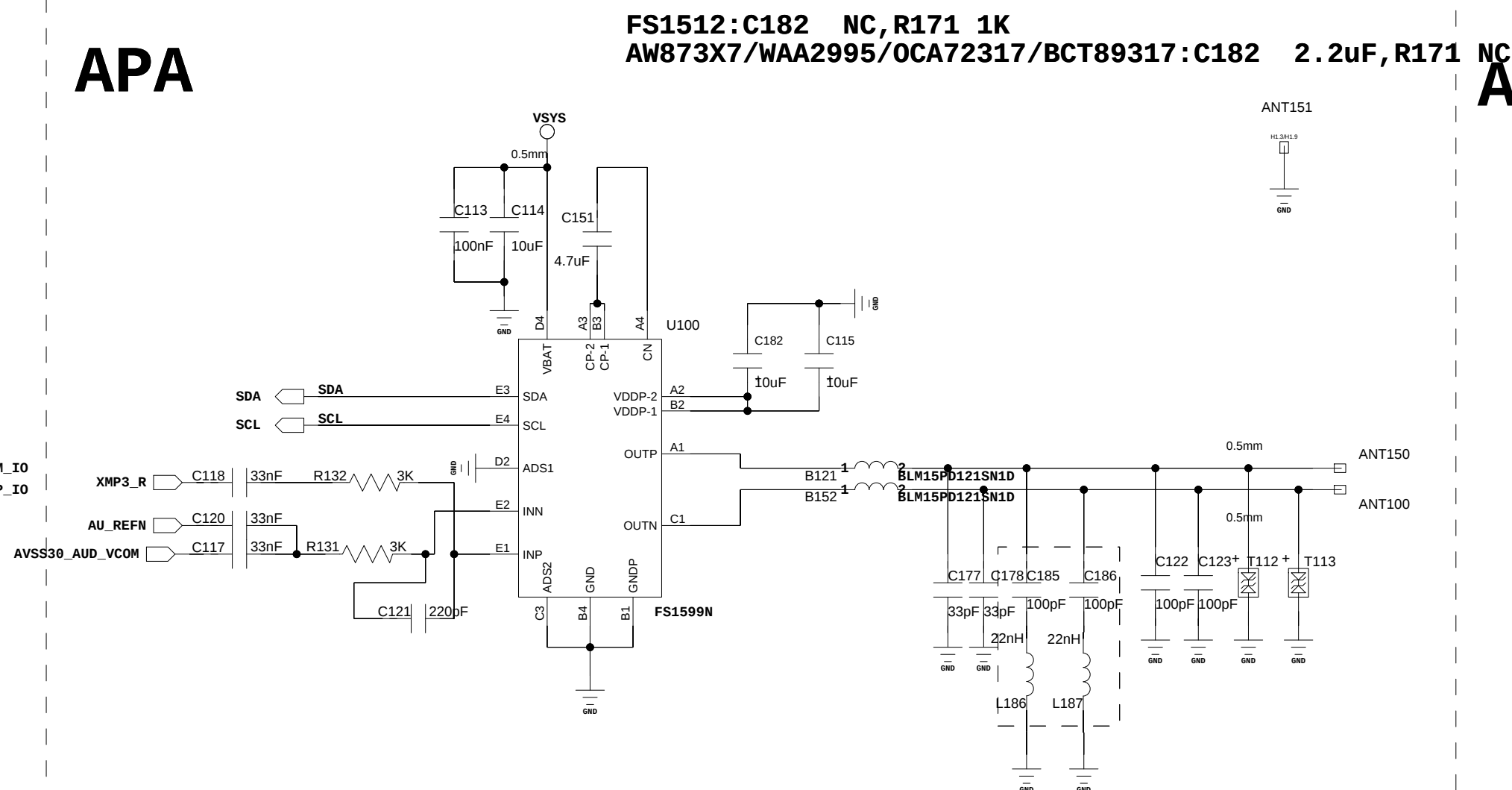


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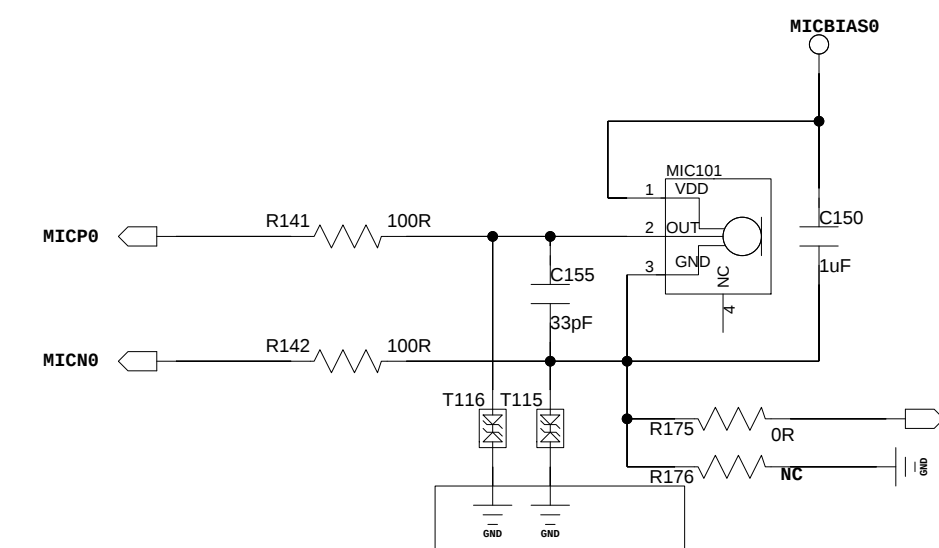
TYPE C



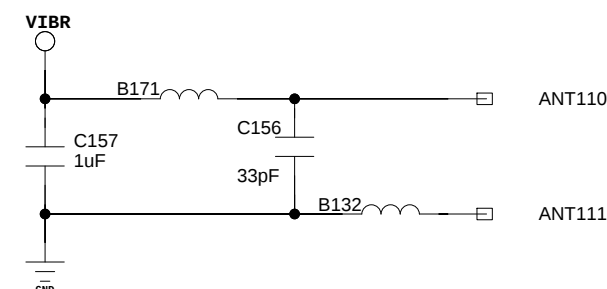
APA



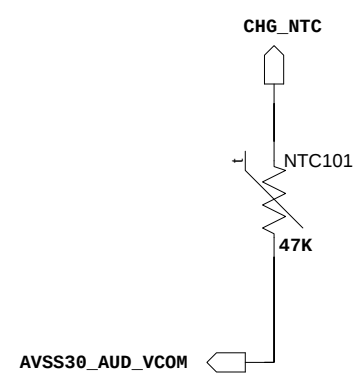
1 NC AUDIO MIC



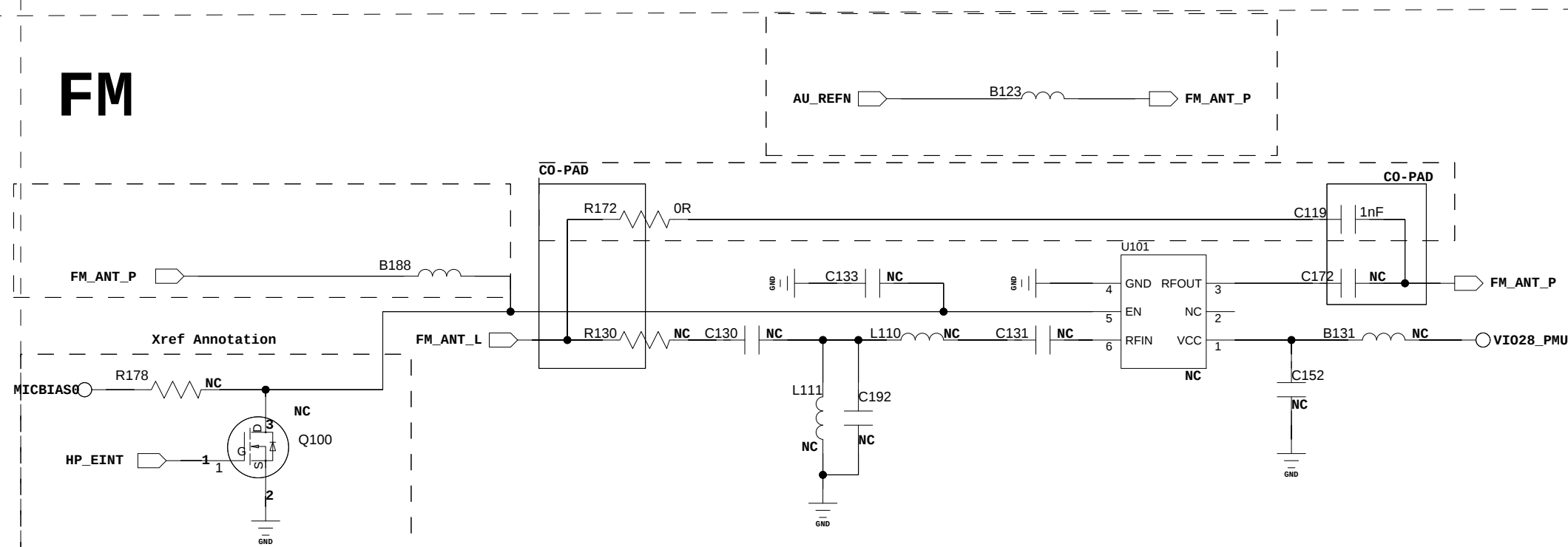
VIBR



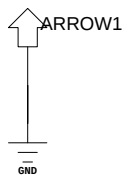
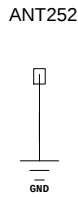
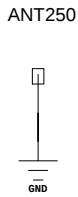
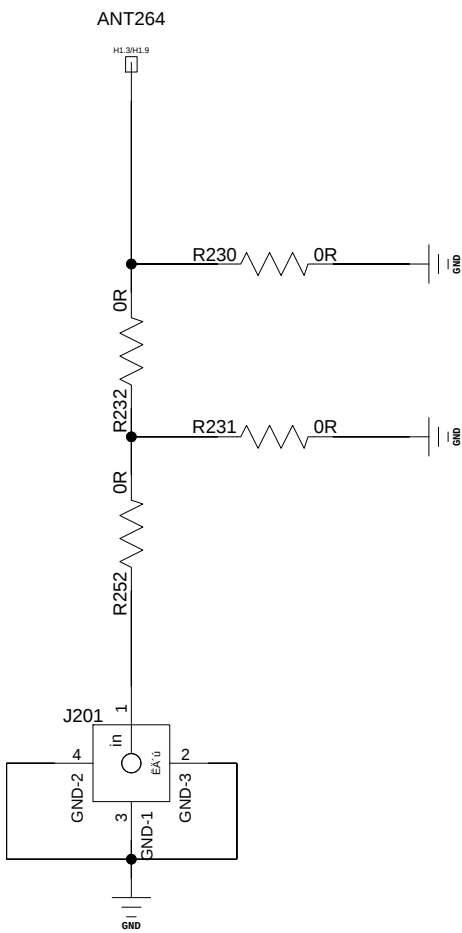
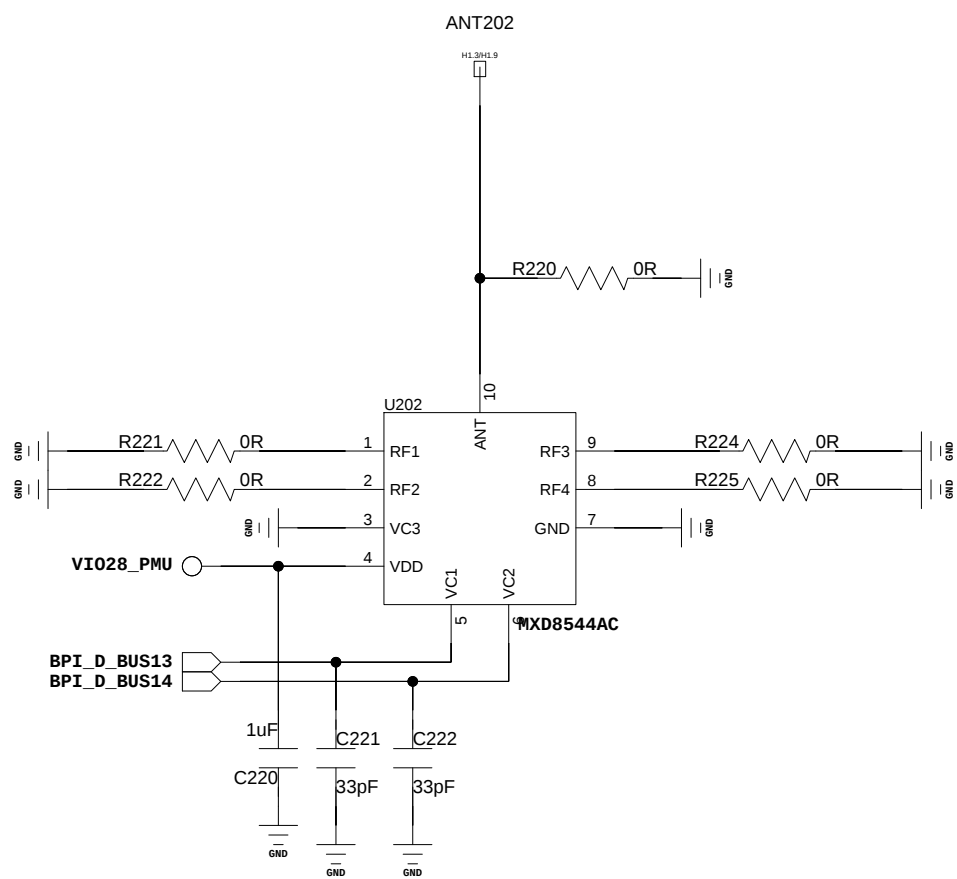
NTC



FM



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SN1

